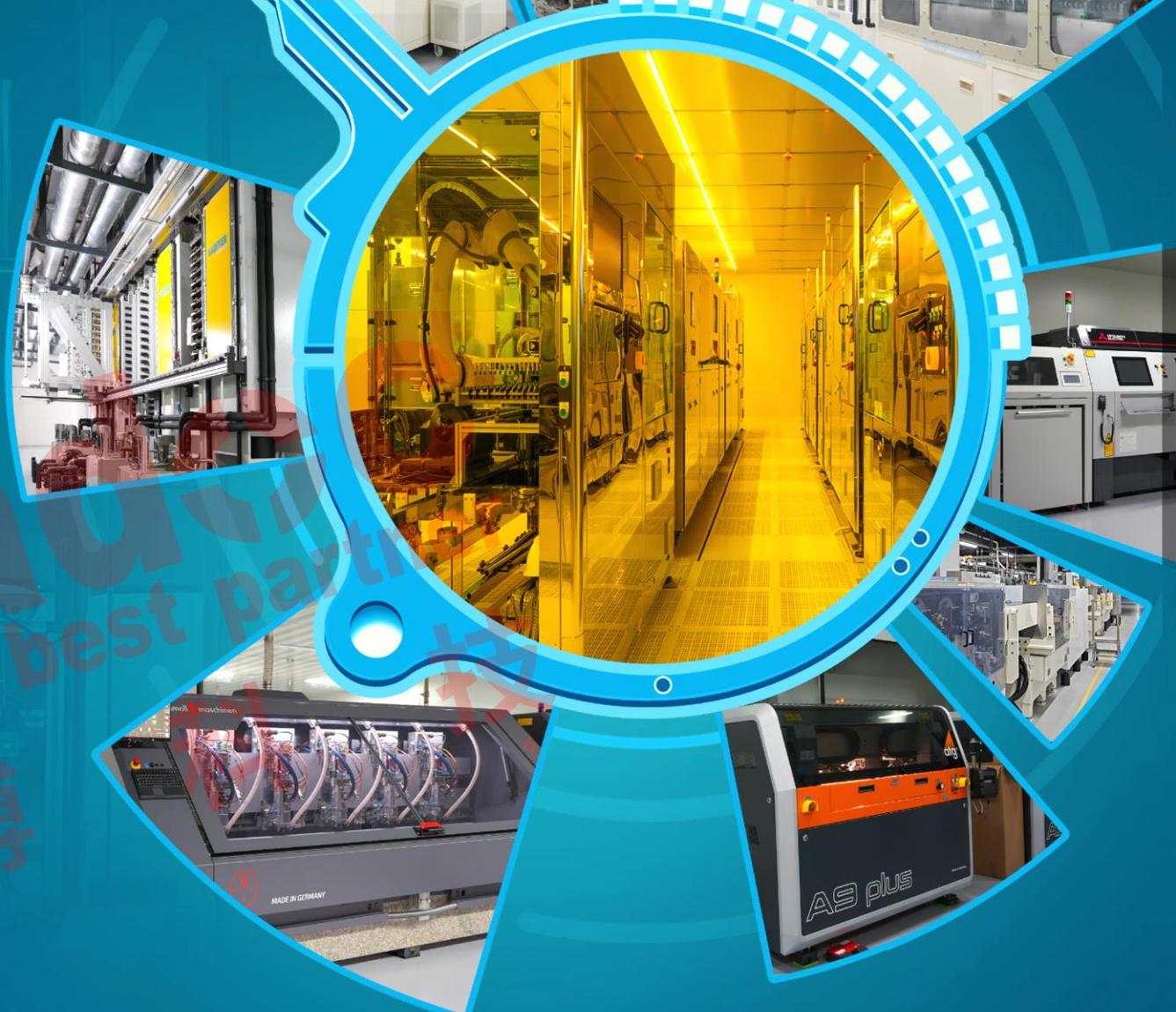


# 深挖阻抗的 细节问题

PCB设计十大误区 (外传3)

一博科技-SI研究部

Edadoc your best partner



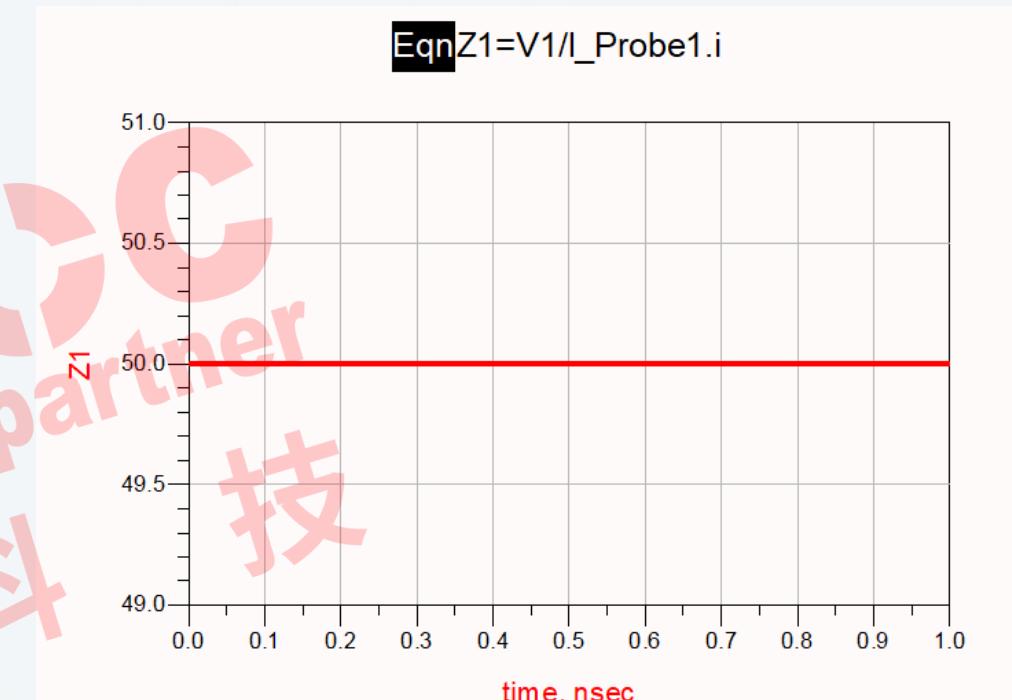
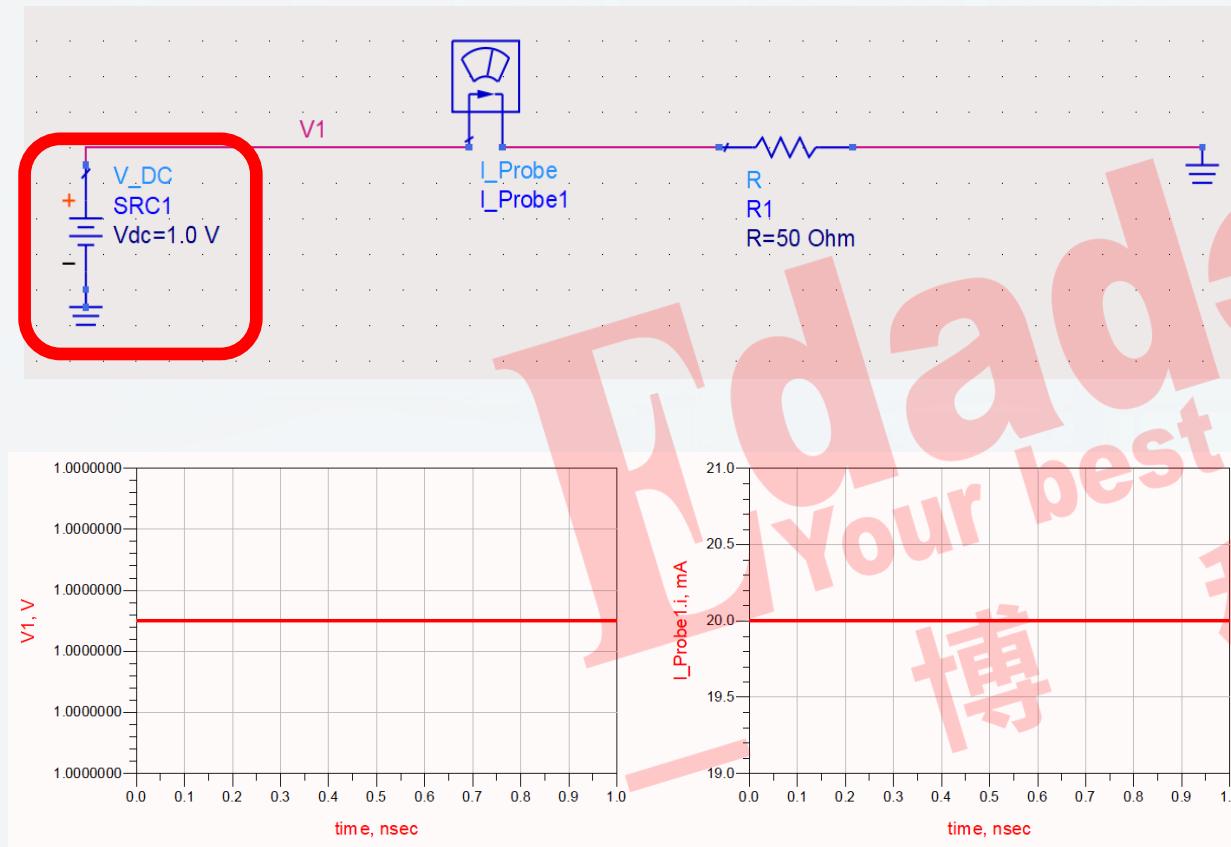
## PART 01

# 阻抗：高速设计的入门

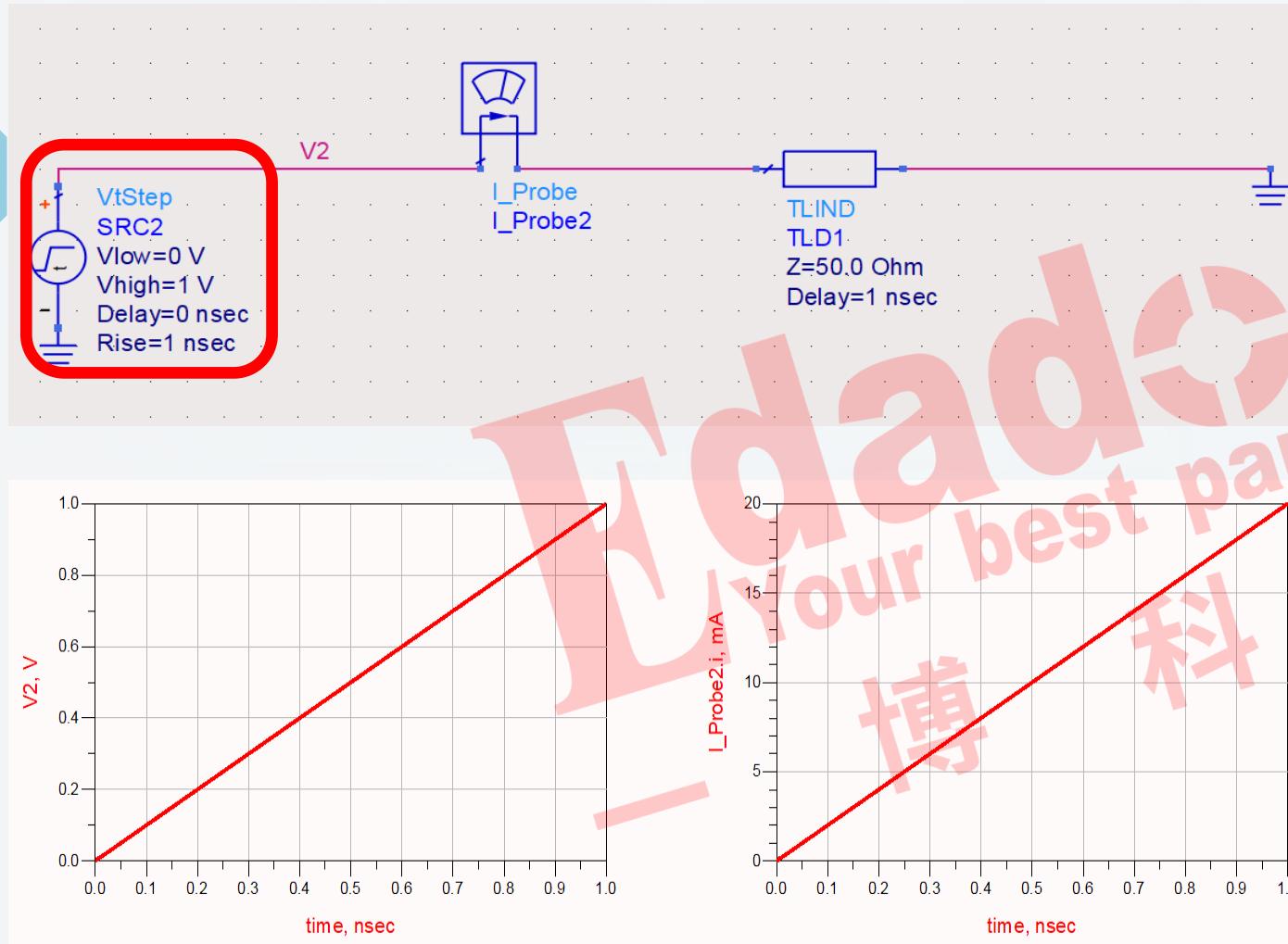


# 电阻与阻抗

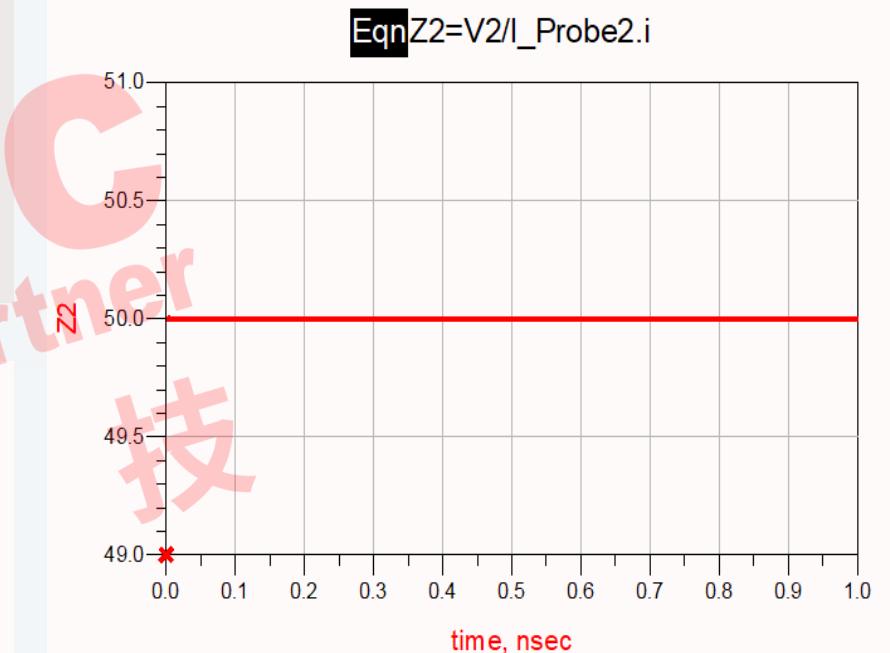
- 到底能不能讲清楚电阻与阻抗的区别？
- 电阻的概念大家估计很好理解



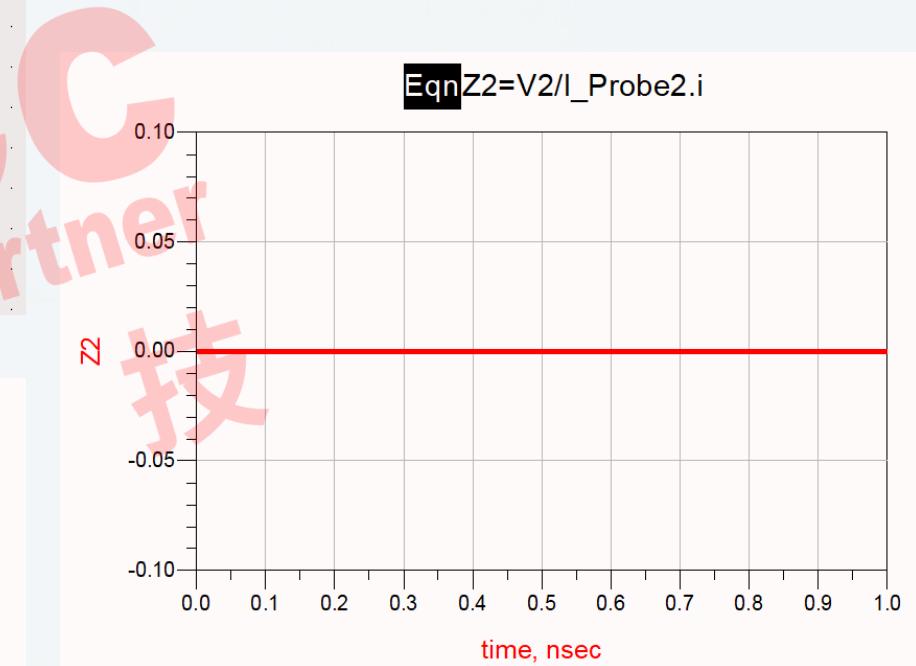
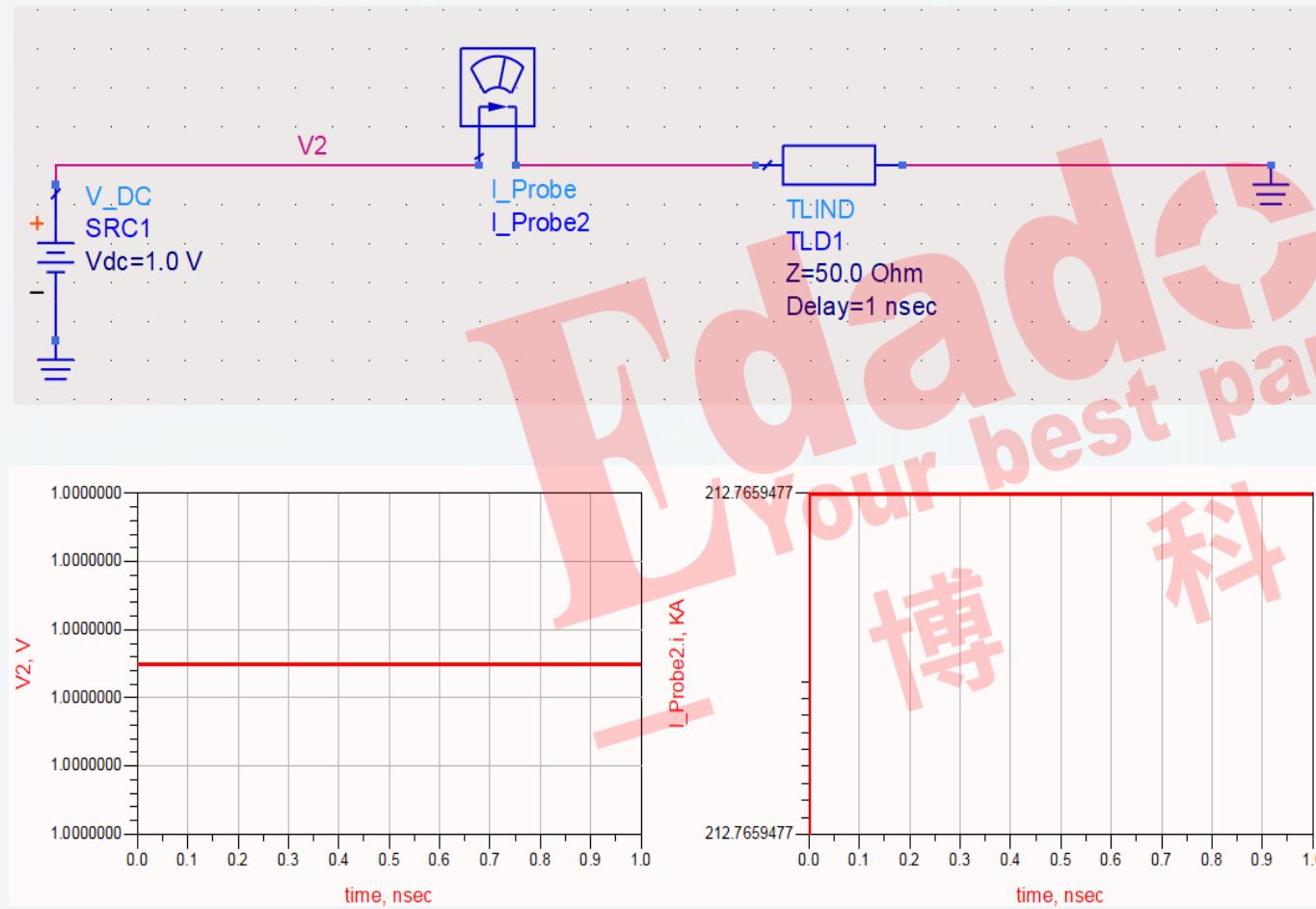
- 那阻抗是怎么表征的呢?



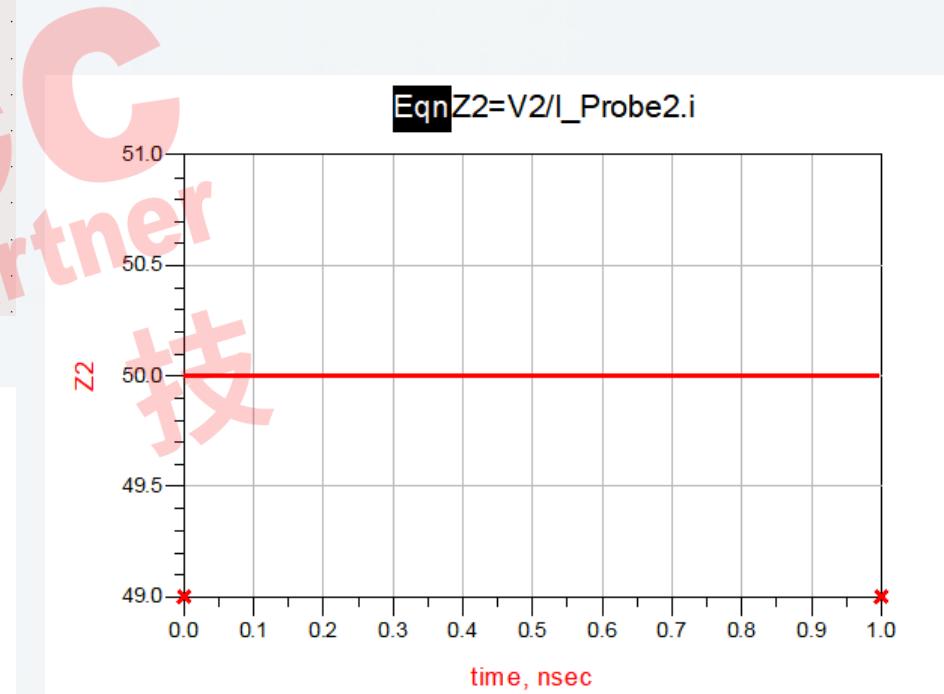
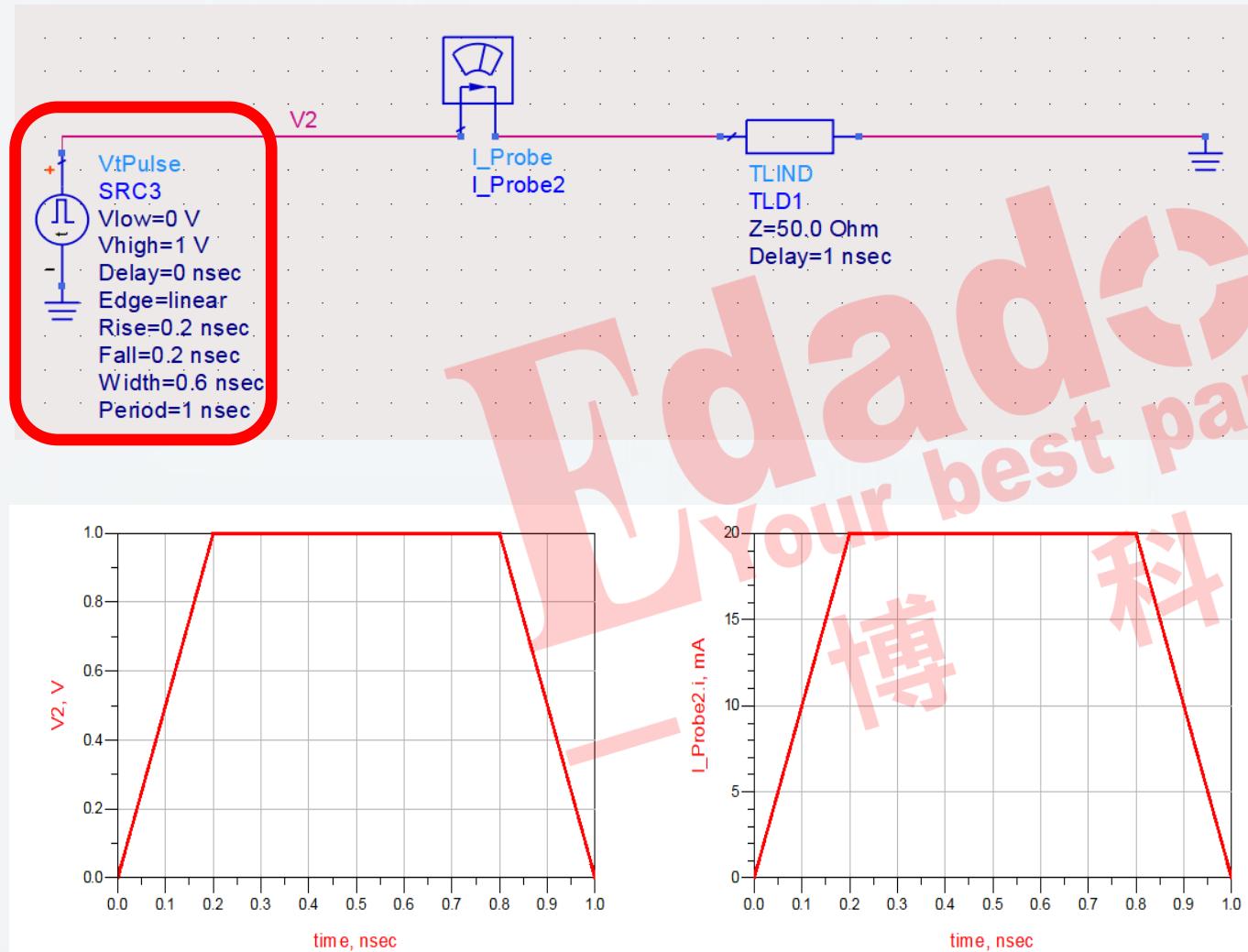
$$\text{Eqn } Z_2 = V_2 / I_{\text{Probe2},i}$$



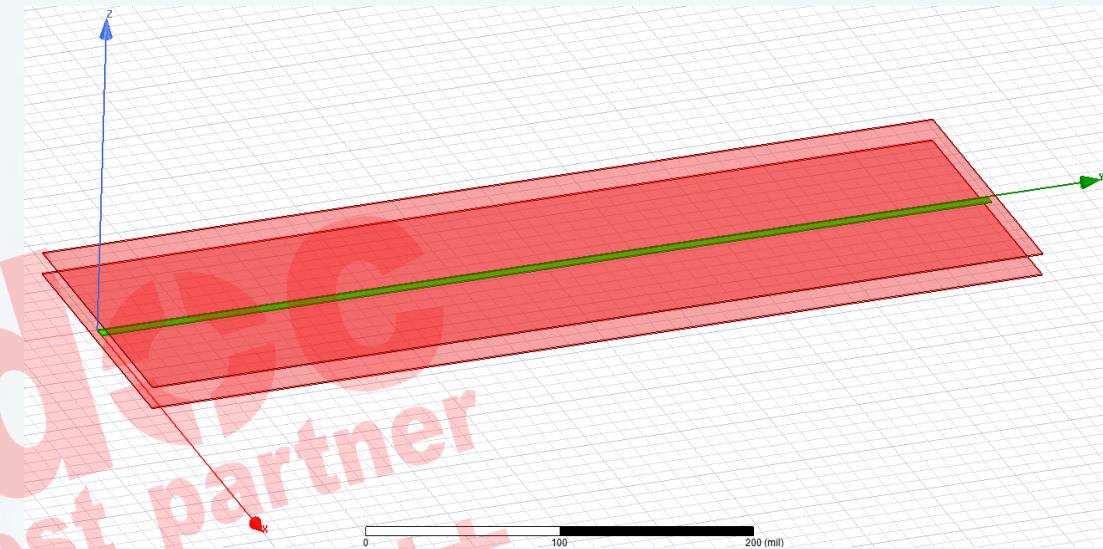
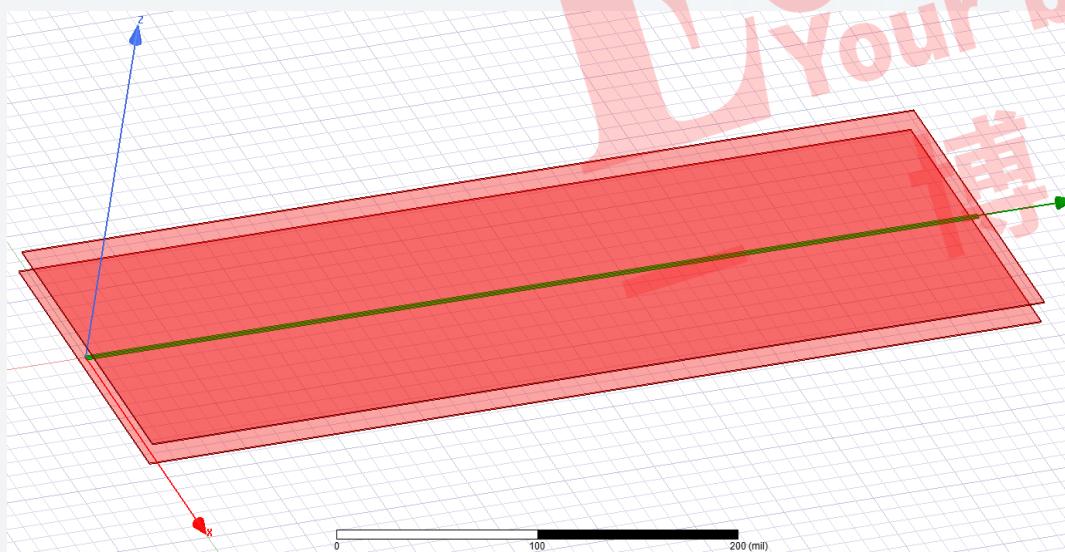
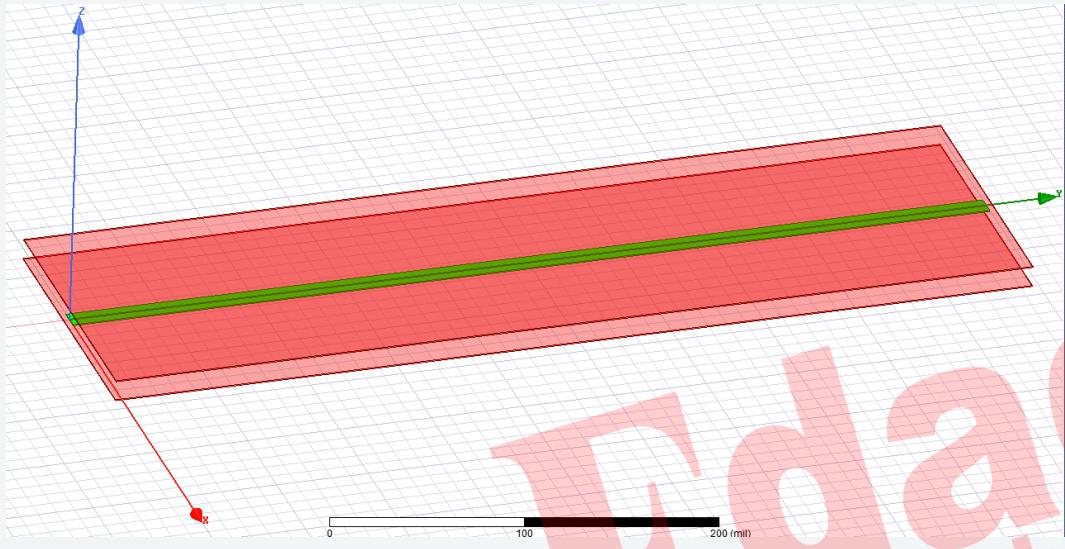
- 什么叫变化的电压或电流才能产生阻抗
- 这样会有阻抗吗？



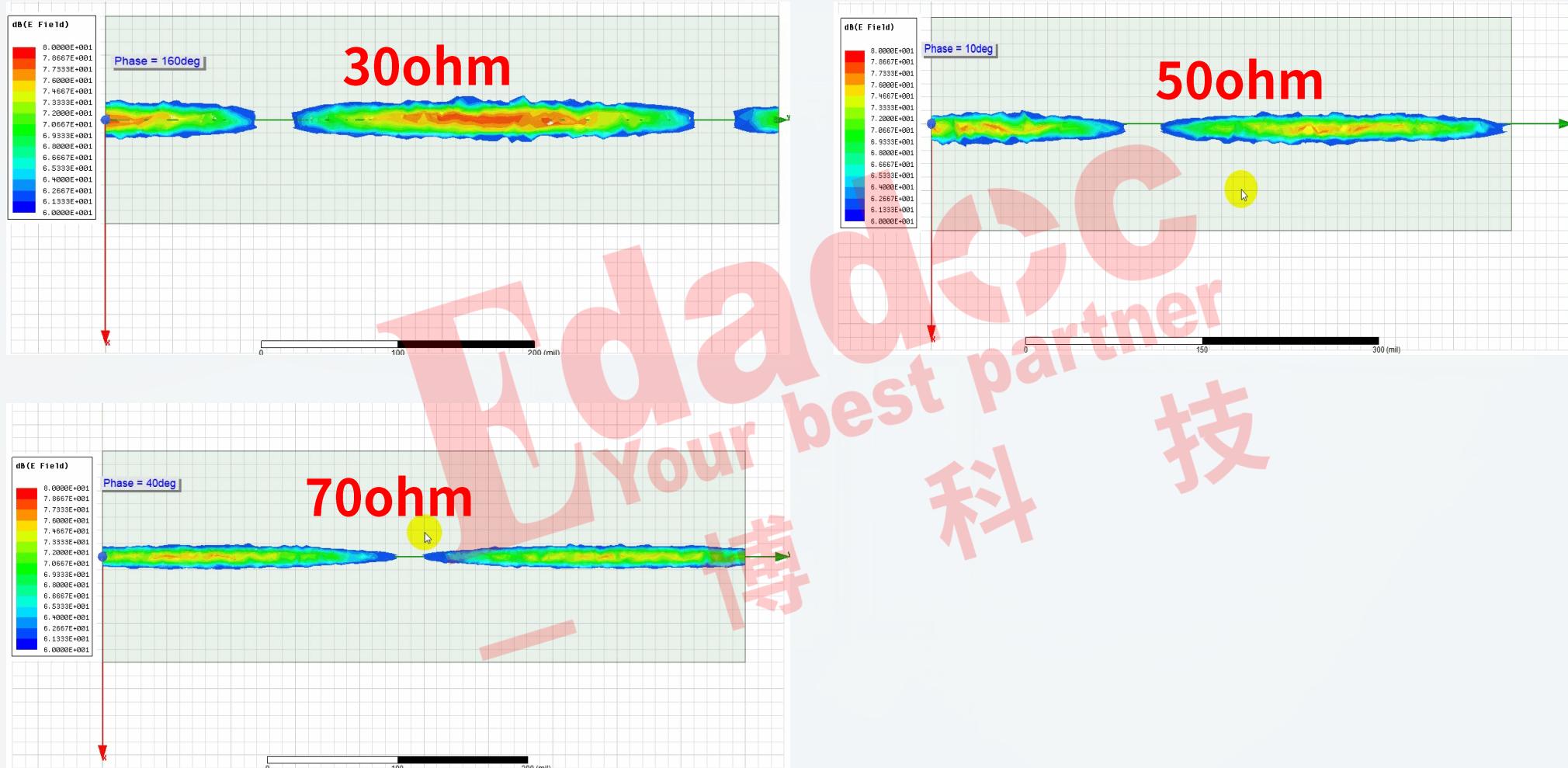
- 一定只能是阶跃信号才能表征出阻抗吗？
- 脉冲信号可以吗？



- 30ohm, 50ohm, 70ohm的3D传输性模型



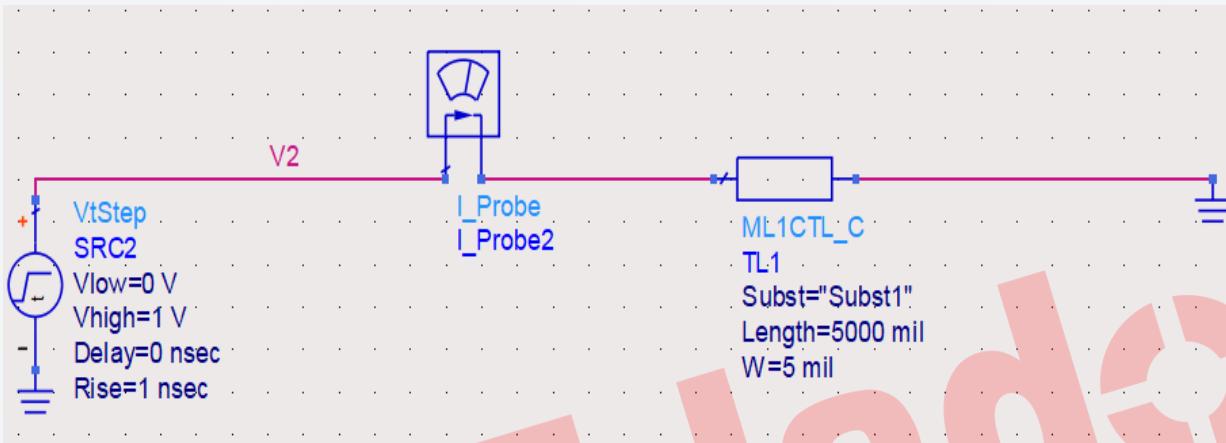
- 阻抗就是阻碍电磁场传输的能力，阻抗不同，阻碍电磁场的程度不同



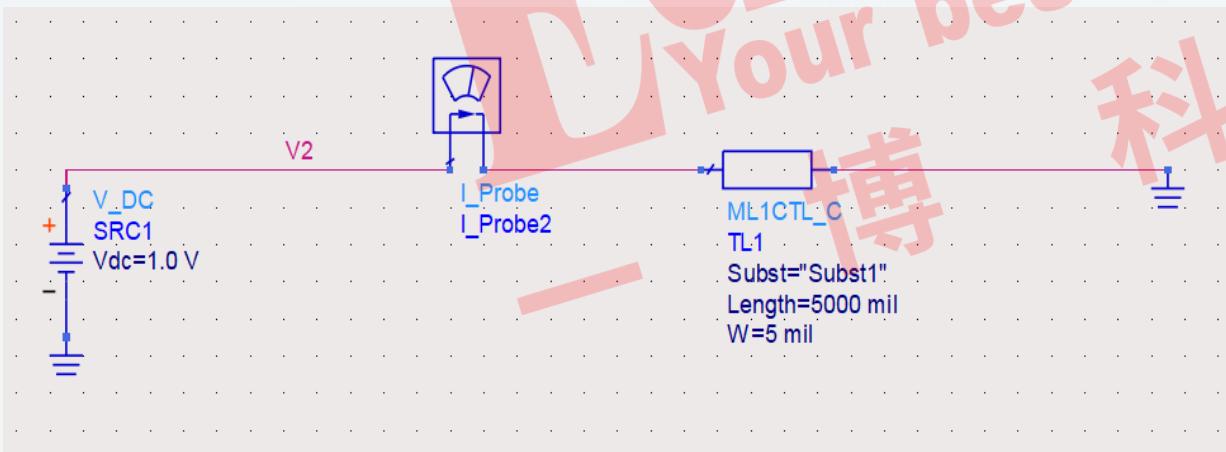
# 电阻和阻抗并存

- 真实的传输线既有电阻又有阻抗……

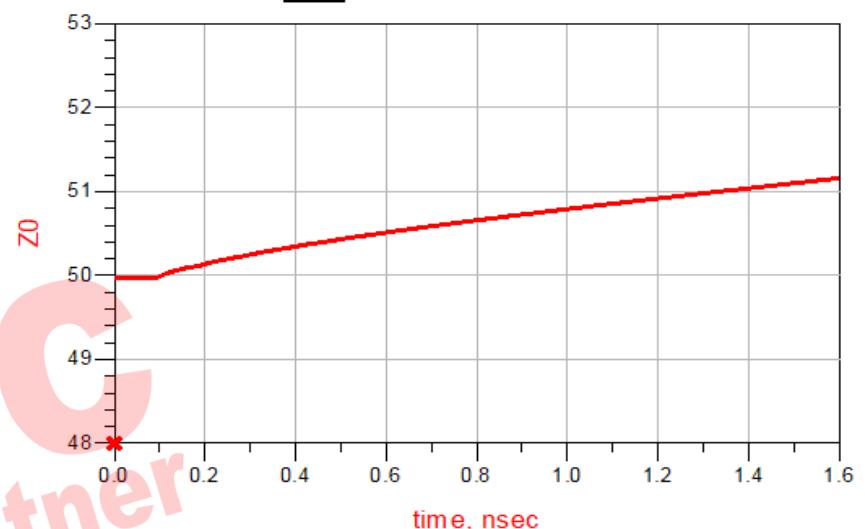
阻抗



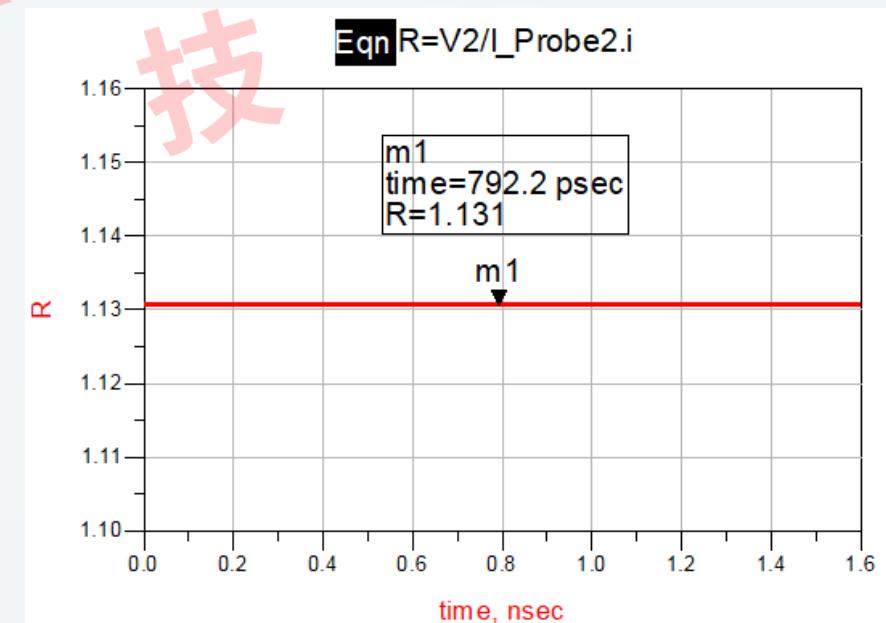
电阻



Eqn  $Z_0 = V_2 / I_{\text{Probe}1.i}$



Eqn  $R = V_2 / I_{\text{Probe}2.i}$

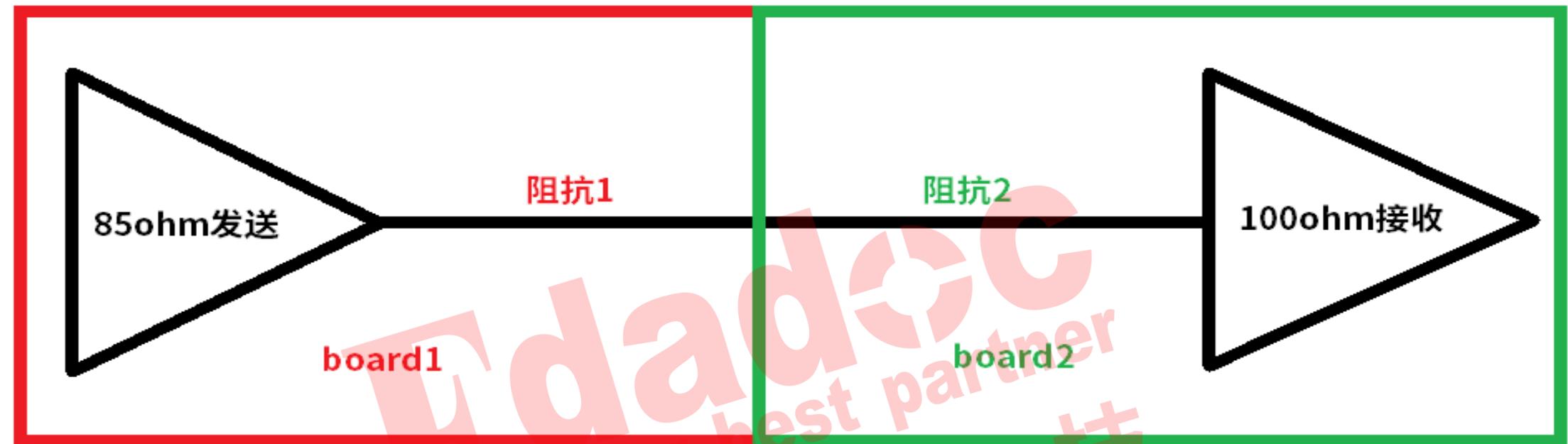


## PART 02

# 设计上选对阻抗值其实更重要

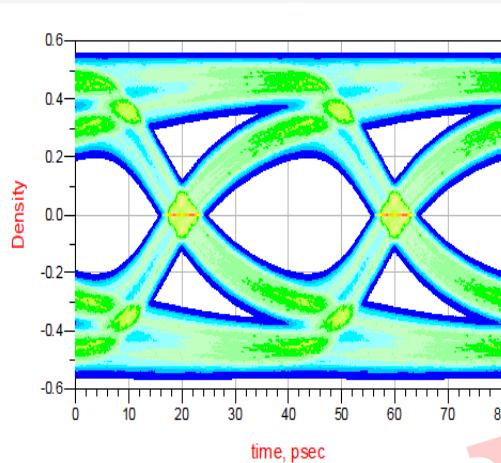


- 两块板的阻抗要怎么控?



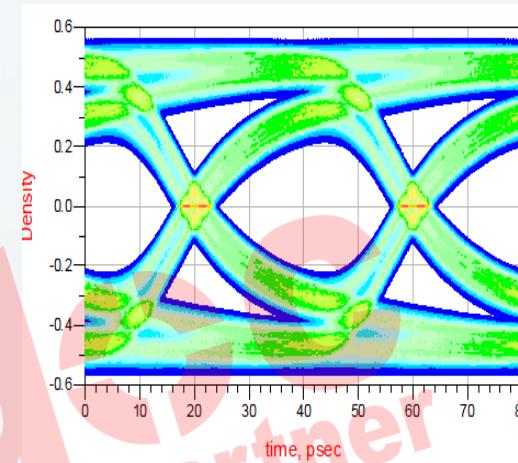
- case1: board1-100ohm, board2-100ohm;
- case2: board1-85ohm, board2-85ohm;
- case3: board1-85ohm, board2-100ohm;
- case4: board1-92.5ohm, board2-92.5ohm;

- 两块板的传输线阻抗控制不同



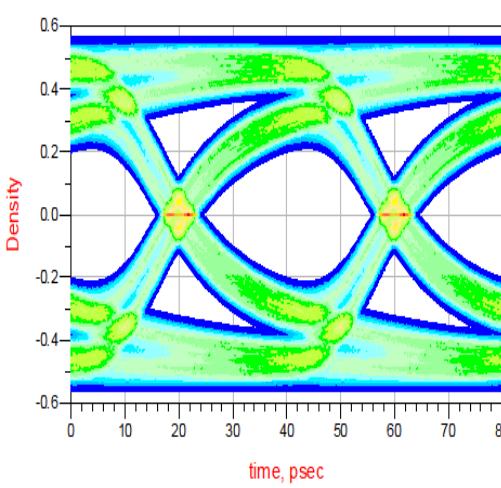
100ohm-100ohm  
眼高: 77mV

measurement	Summary
Level1	0.377
Level0	-0.376
Height	0.337
Width	3.100E-11
WidthAtBER	1.560E-11
HeightAtBER	0.077



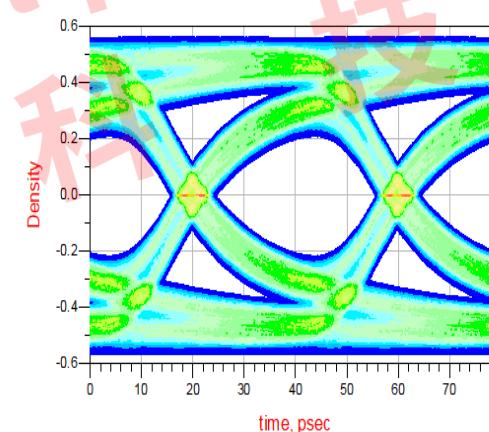
85ohm-85ohm  
眼高: 135mV

measurement	Summary
Level1	0.386
Level0	-0.385
Height	0.367
Width	3.160E-11
WidthAtBER	1.840E-11
HeightAtBER	0.135



85ohm-100ohm  
眼高: 102mV

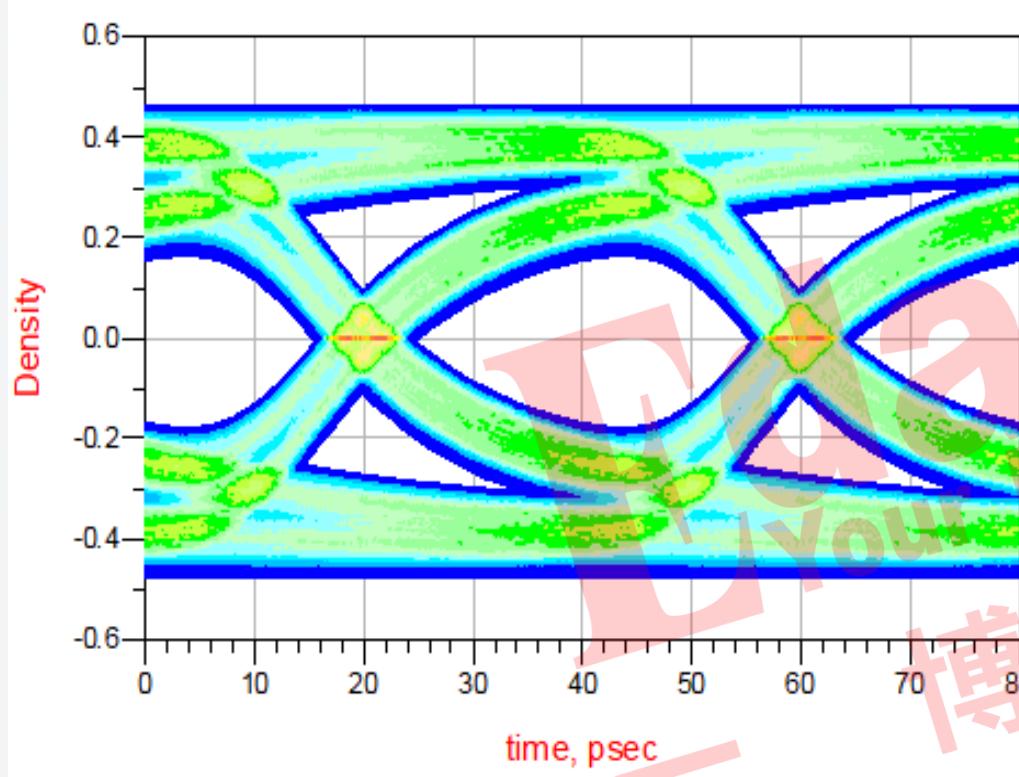
measurement	Summary
Level1	0.383
Level0	-0.382
Height	0.350
Width	3.160E-11
WidthAtBER	1.700E-11
HeightAtBER	0.102



92.5ohm-92.5ohm  
眼高: 109mV

measurement	Summary
Level1	0.382
Level0	-0.382
Height	0.355
Width	3.140E-11
WidthAtBER	1.740E-11
HeightAtBER	0.109

- 如果搞反了, case5: board1-100ohm, board2-85ohm;

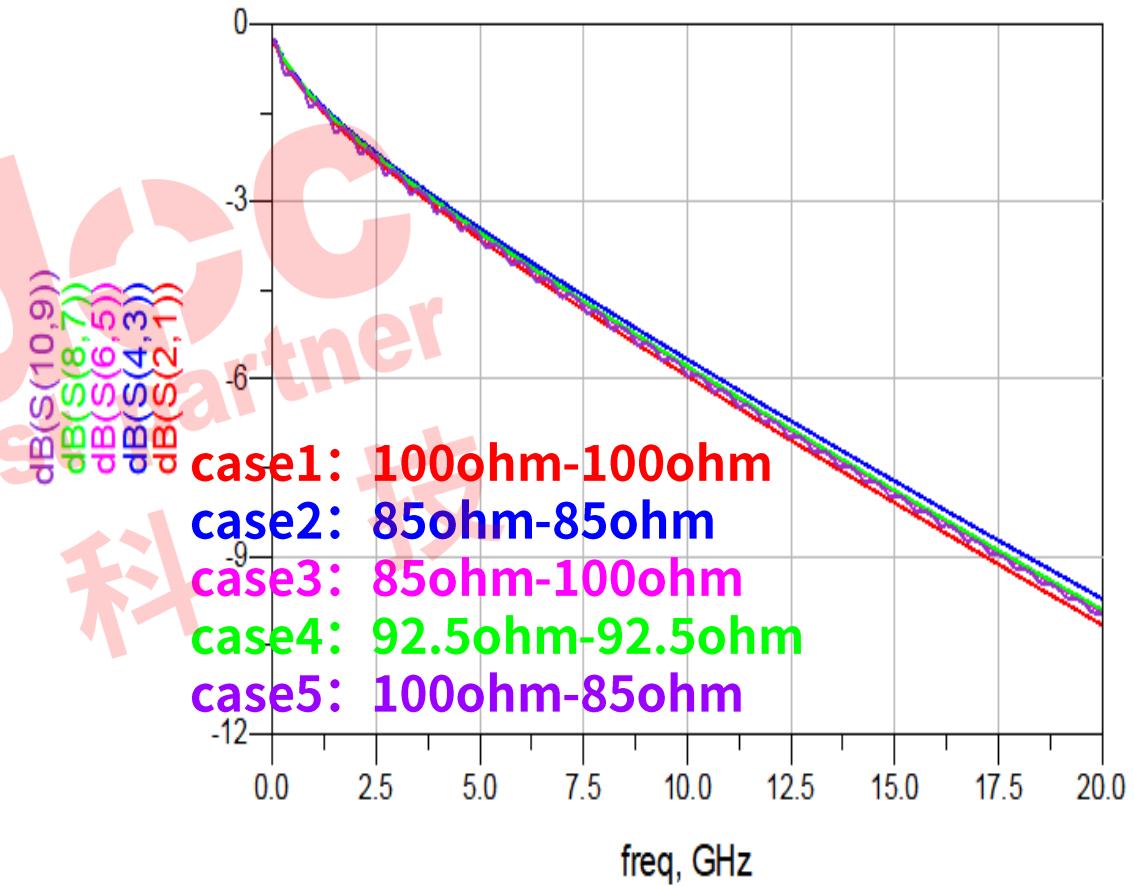
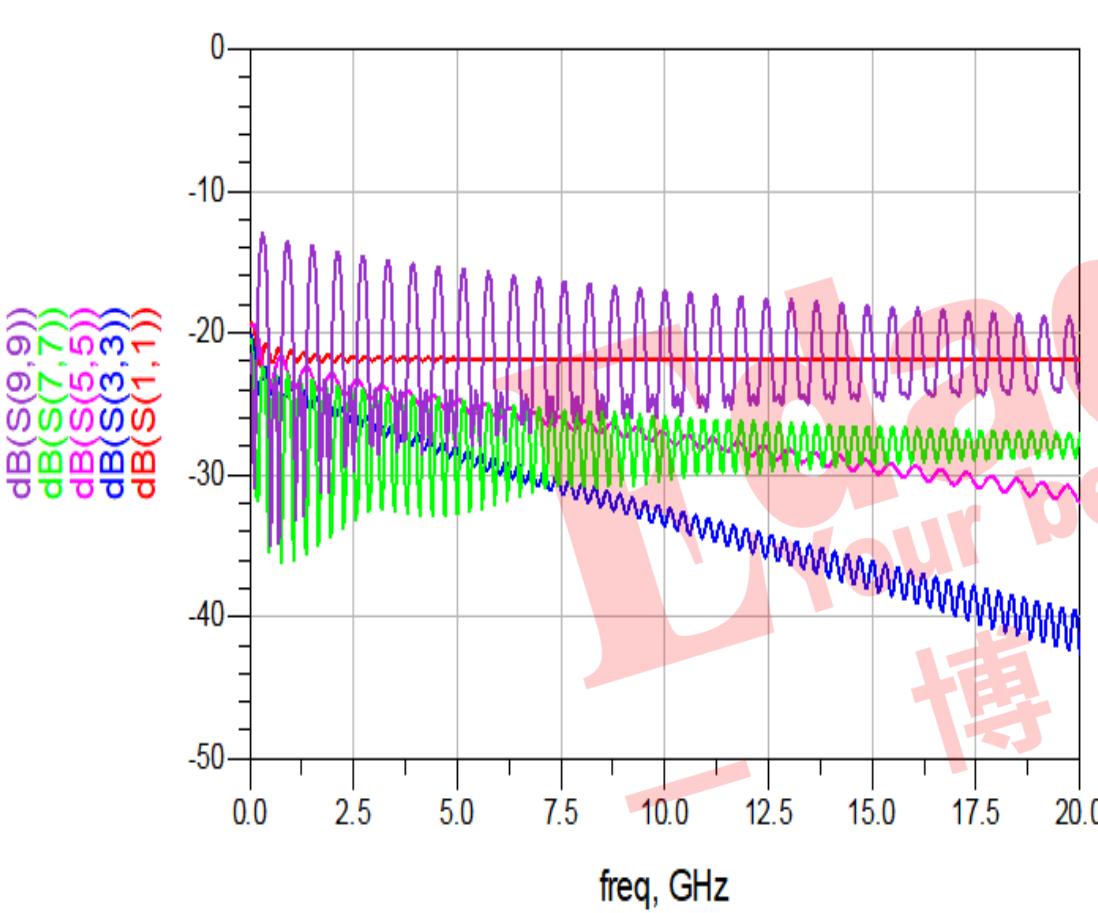


measurement	Summary
Level1	0.317
Level0	-0.317
Height	0.283
Width	3.100E-11
WidthAtBER	1.640E-11
HeightAtBER	0.080

100ohm-85ohm  
眼高: 80mV

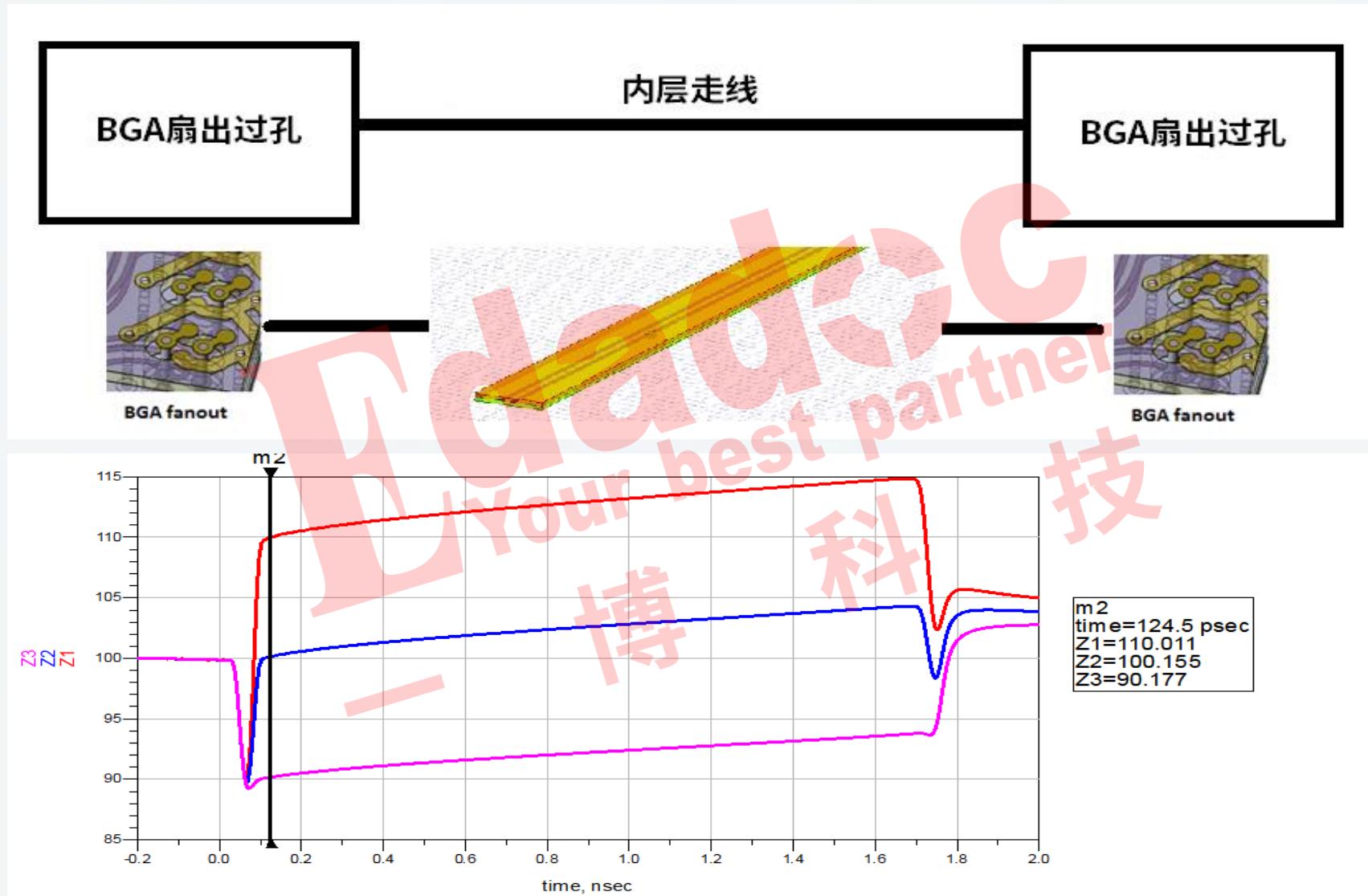
# 两端芯片内阻不一样

- 从插损回损上找原因

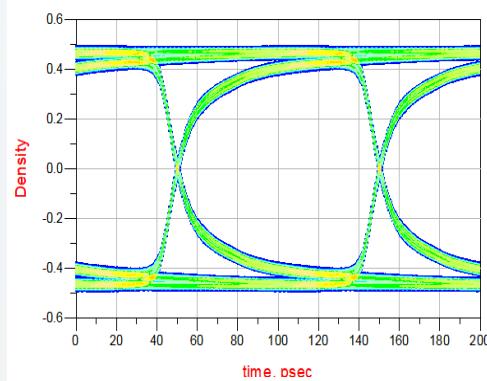


# 100欧姆真的是最好的吗？

- 两端的过孔只能优化到90欧姆的情况下，传输线的阻抗控100是最好的吗？

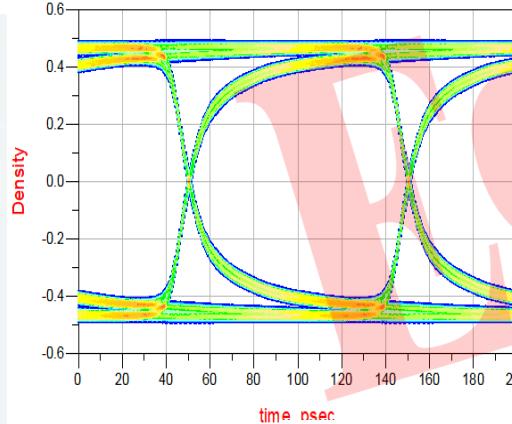


- 10G信号的眼图结果



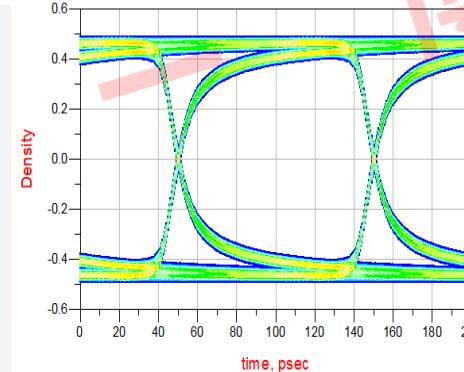
measurement	Summary
Level1	0.436
Level0	-0.436
Height	0.722
Width	9.850E-11
WidthAtBER	9.700E-11
HeightAtBER	0.784

110欧姆：眼高784mV



measurement	Summary
Level1	0.437
Level0	-0.437
Height	0.731
Width	9.800E-11
WidthAtBER	9.750E-11
HeightAtBER	0.794

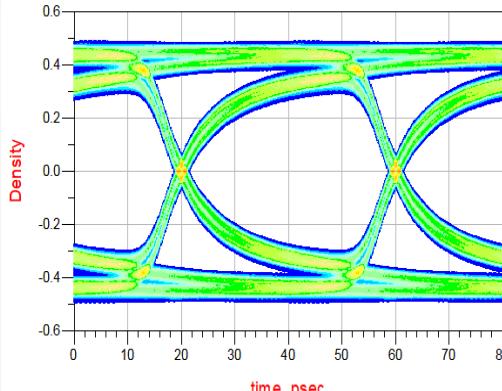
100欧姆：眼高794mV



measurement	Summary
Level1	0.435
Level0	-0.435
Height	0.724
Width	9.850E-11
WidthAtBER	9.700E-11
HeightAtBER	0.784

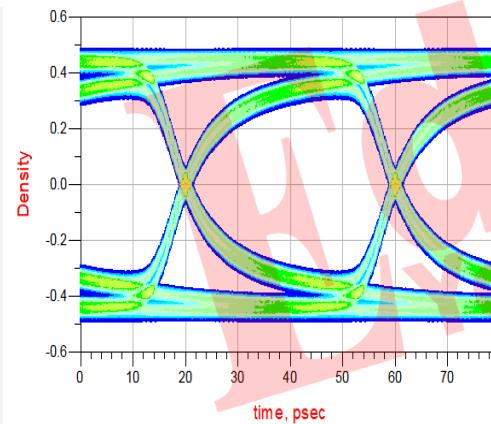
90欧姆：眼高784mV

- 25G信号的眼图结果



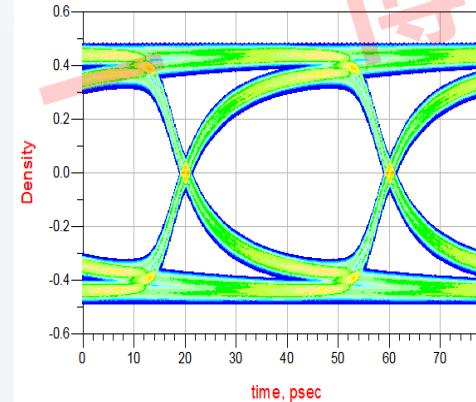
measurement	Summary
Level1	0.382
Level0	-0.382
Height	0.508
Width	3.740E-11
WidthAtBER	3.640E-11
HeightAtBER	0.556

110欧姆：眼高556mV



measurement	Summary
Level1	0.389
Level0	-0.389
Height	0.538
Width	3.760E-11
WidthAtBER	3.680E-11
HeightAtBER	0.587

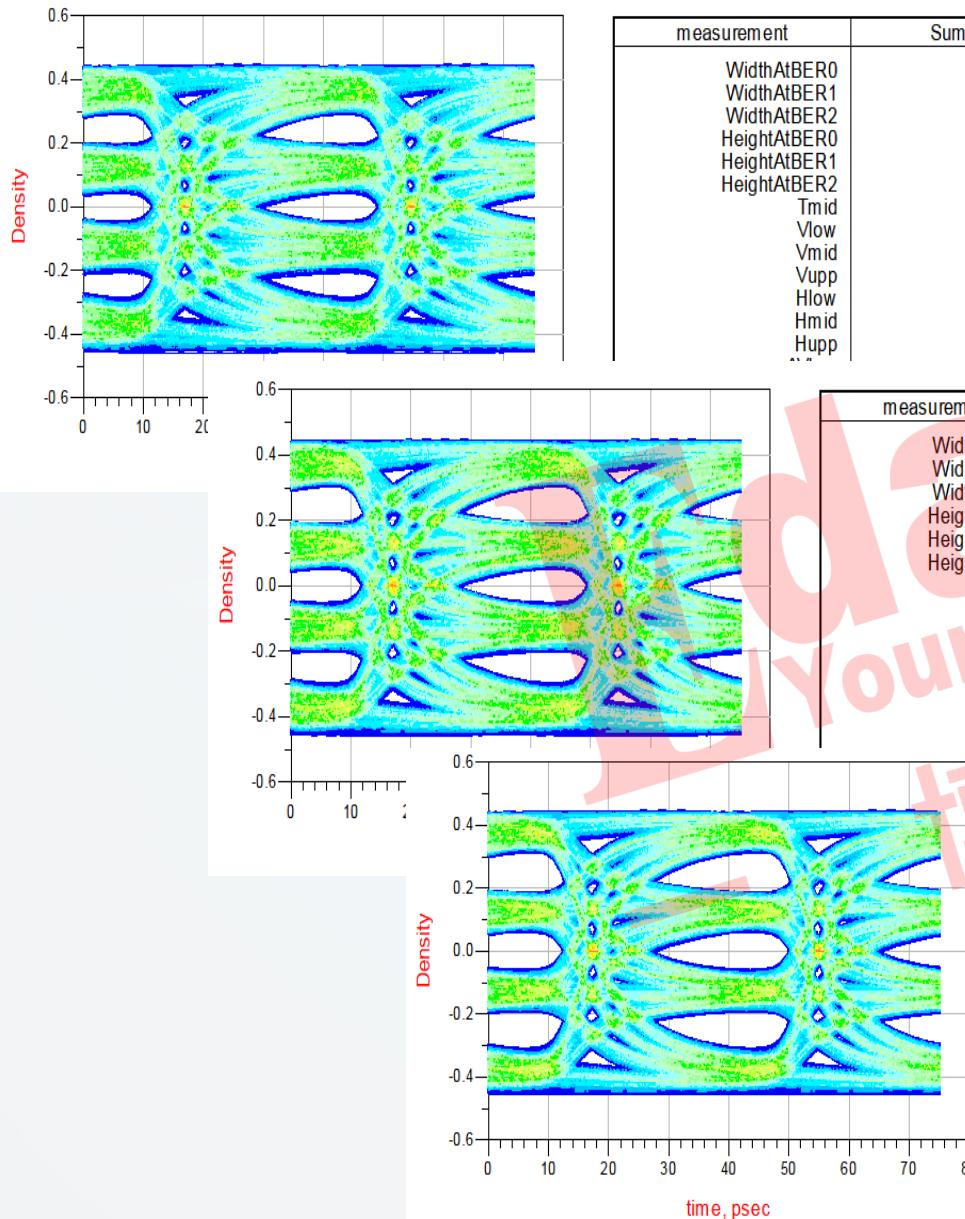
100欧姆：眼高587mV



measurement	Summary
Level1	0.394
Level0	-0.394
Height	0.563
Width	3.760E-11
WidthAtBER	3.700E-11
HeightAtBER	0.608

90欧姆：眼高608mV

- 56G-PAM4信号的眼图结果



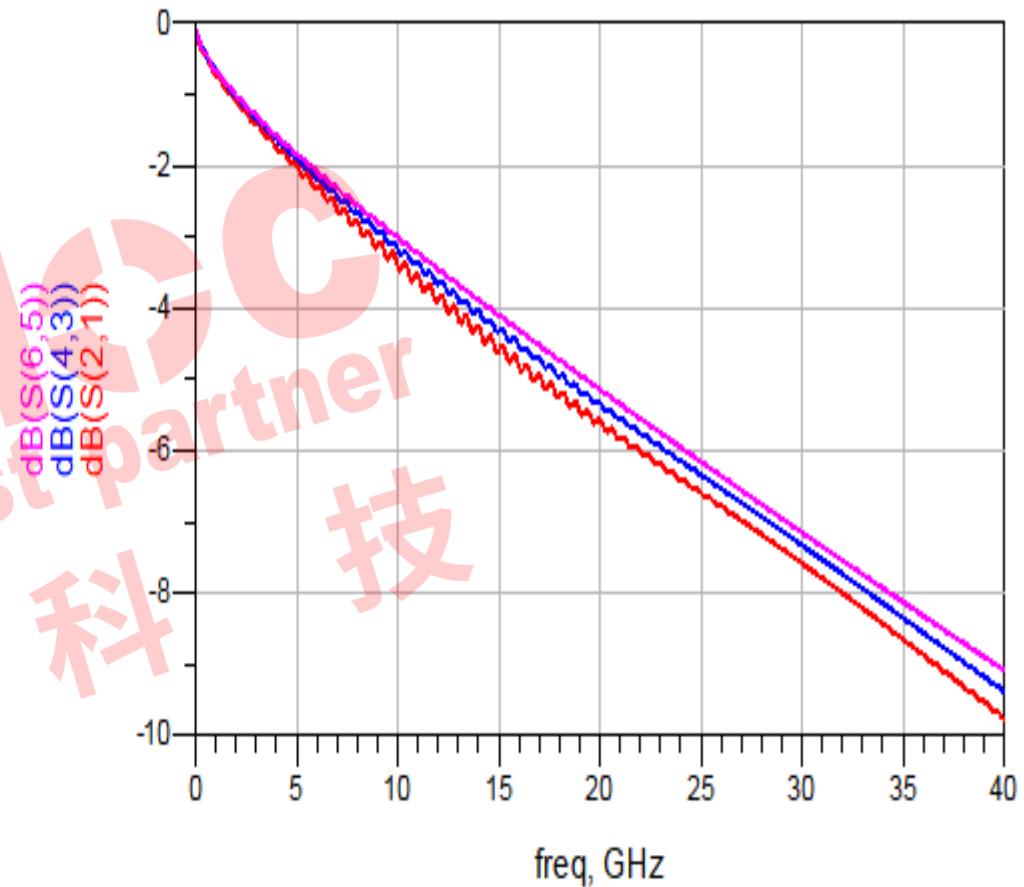
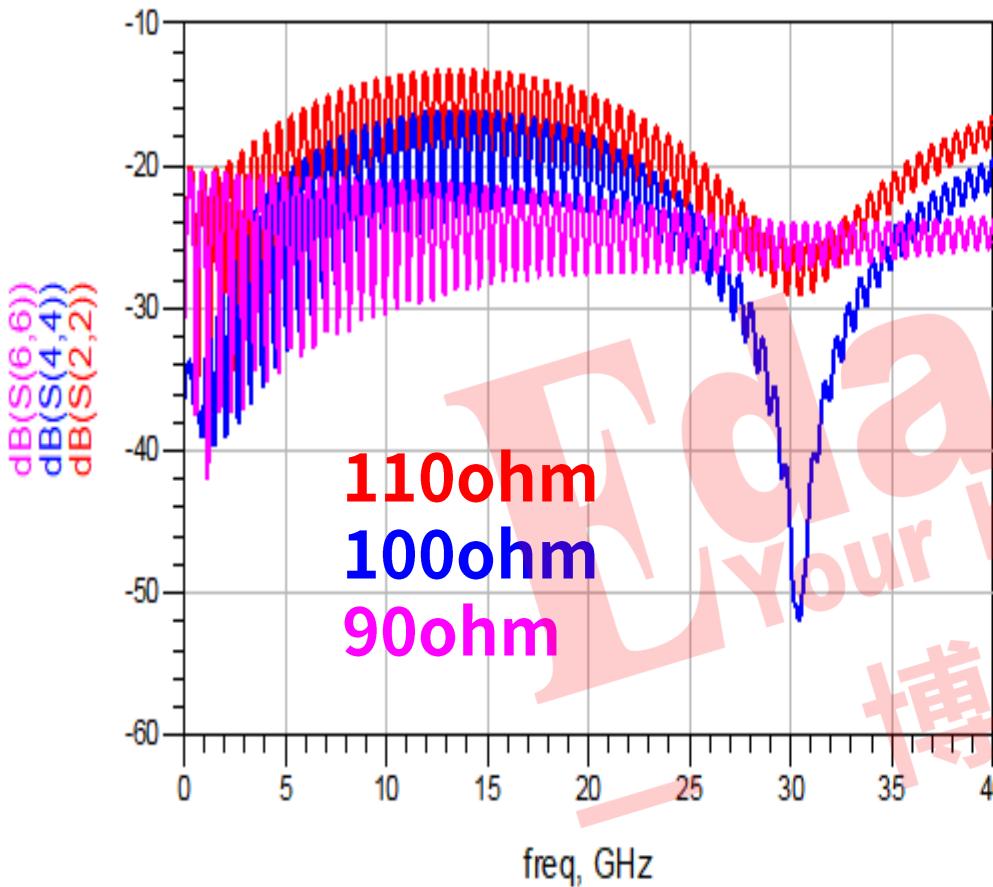
110欧姆: 眼高29mV

100欧姆: 眼高50mV

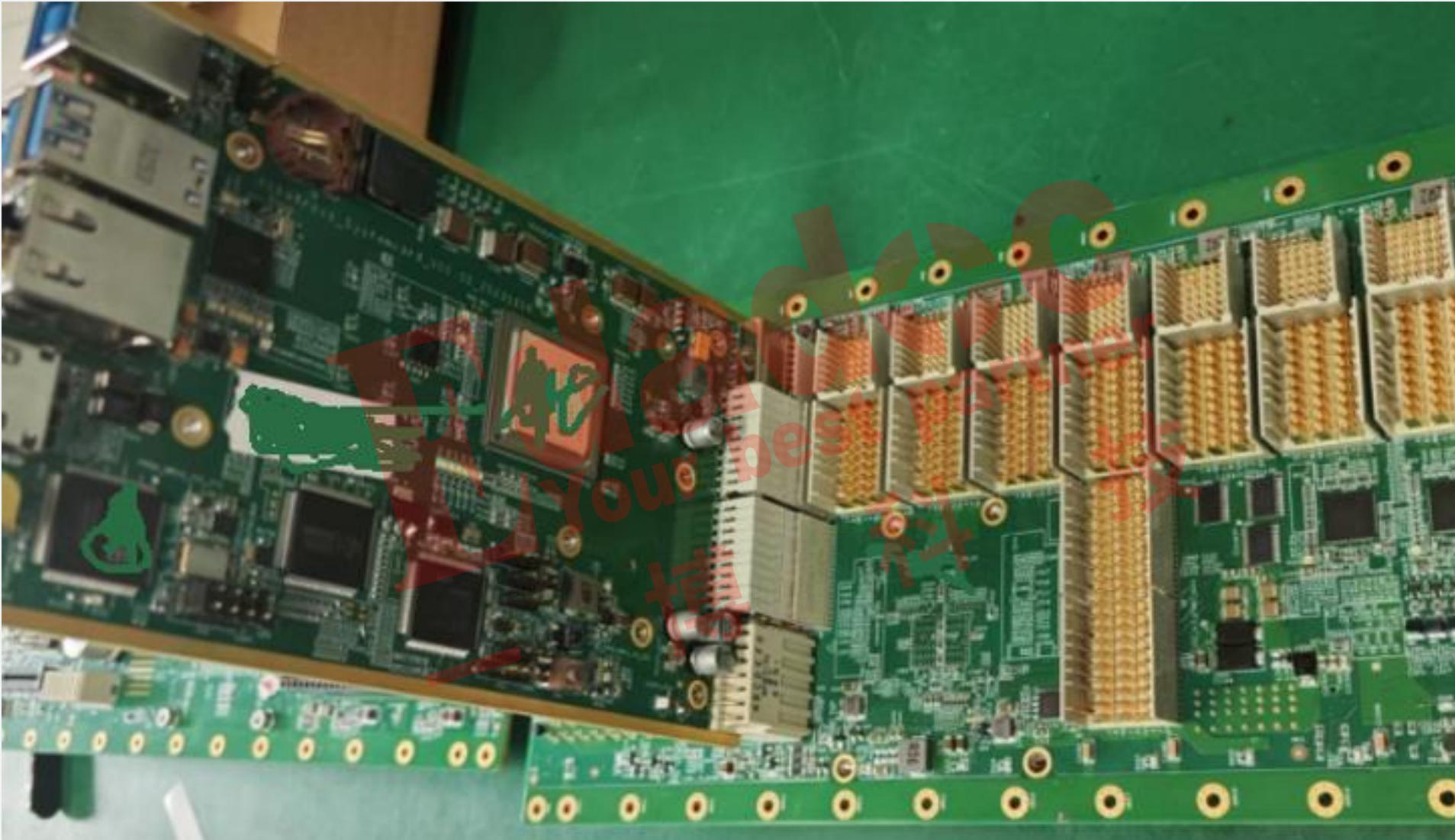
90欧姆: 眼高71mV

# 100欧姆真的是最好吗？

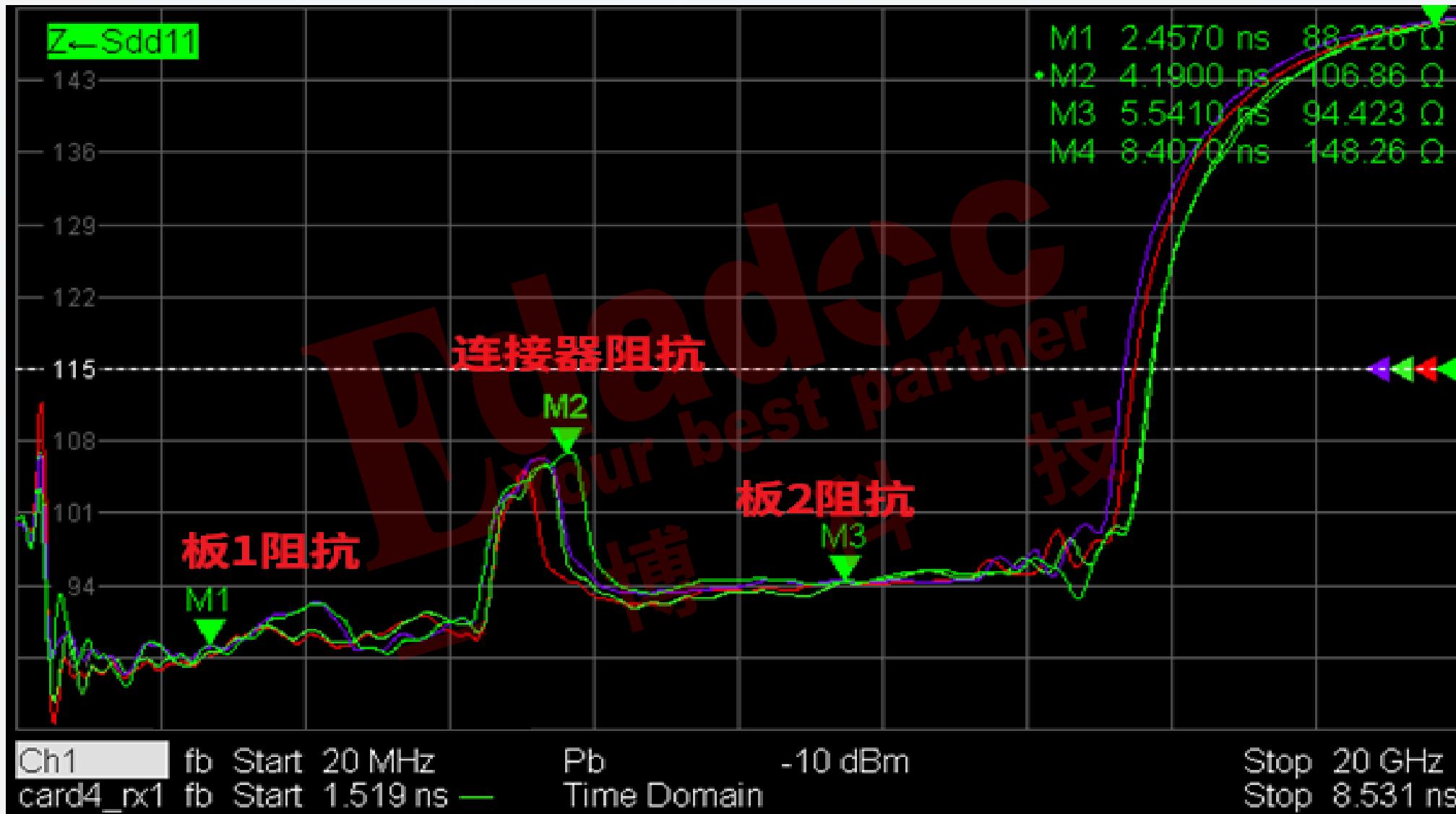
- 从插损回损来看就能知道原因。。。



- PCIE信号通过连接器连接两块板子



- 另外一个真实案例
- 测试结果：中间连接器阻抗105欧姆



## 仿真链路搭建

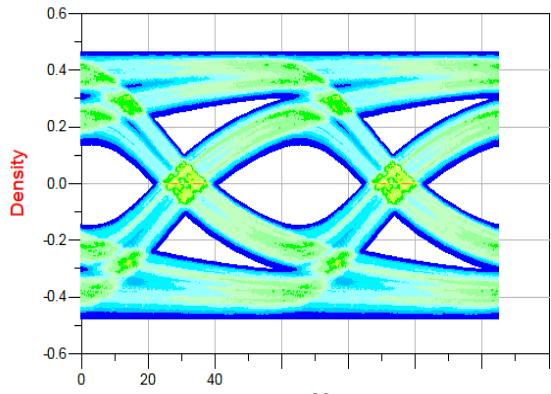
- 连接器阻抗105欧姆，收发芯片内阻85欧姆情况下两块板的传输线阻抗该控制多少欧姆？



- 两块板子分别按照100欧姆, 92.5欧姆和85欧姆来控制的全链路阻抗结果

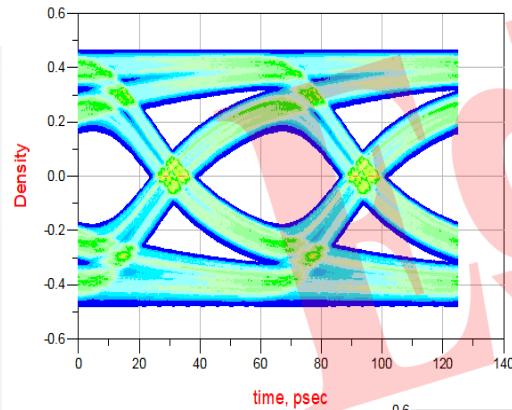


- 不同阻抗下PCIE4.0信号眼图仿真结果对比



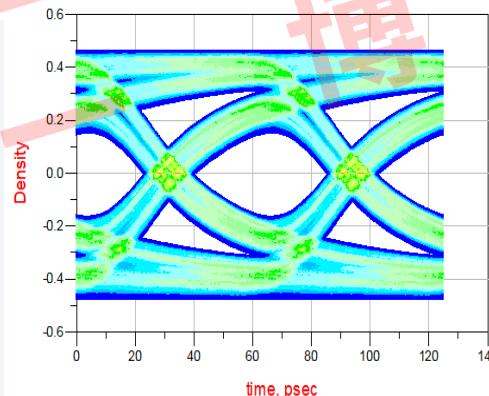
measurement	Summary
Level1	0.304
Level0	-0.303
Height	0.237
Width	4.406E-11
WidthAtBER	1.406E-11
HeightAtBER	0.033

100欧姆：眼高33mV



measurement	Summary
Level1	0.317
Level0	-0.317
Height	0.281
Width	4.719E-11
WidthAtBER	2.531E-11
HeightAtBER	0.116

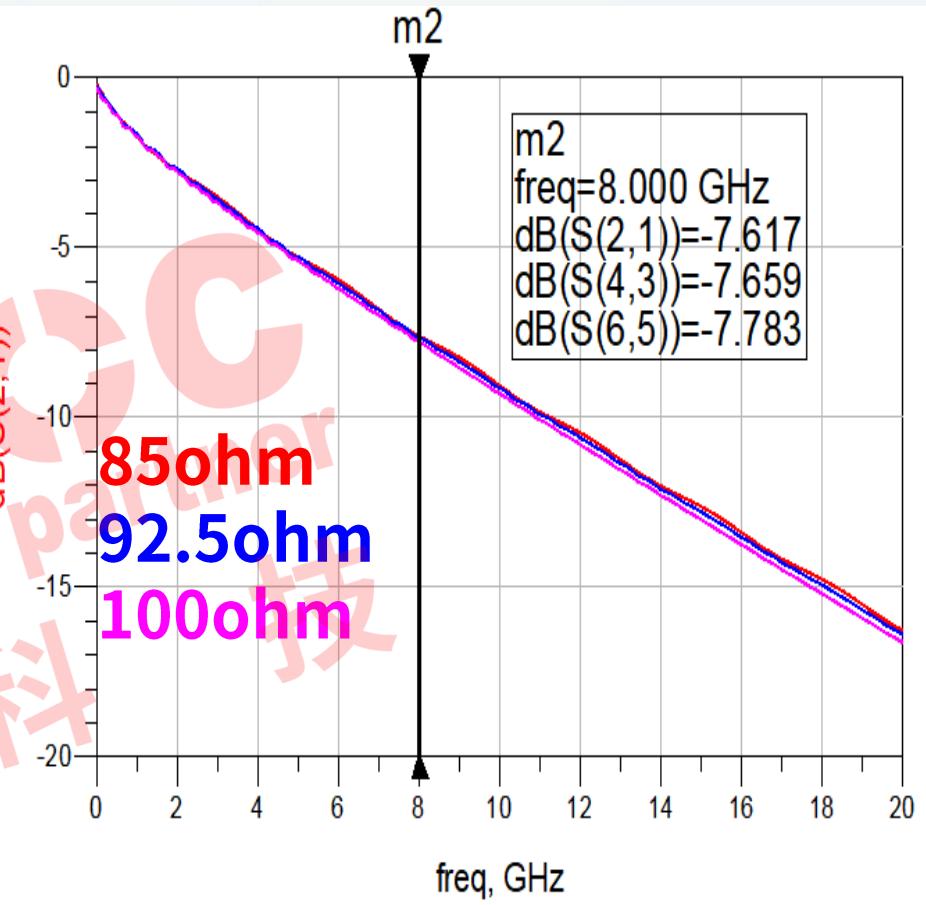
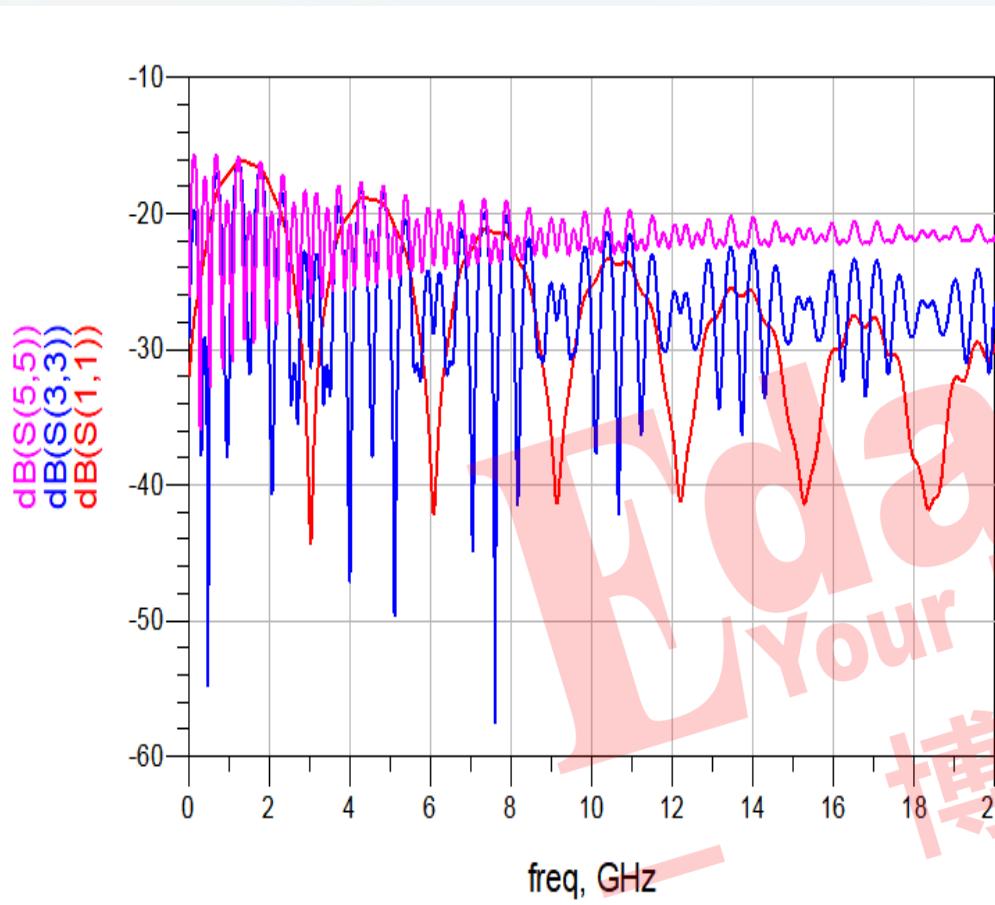
92.5欧姆：眼高116mV



measurement	Summary
Level1	0.311
Level0	-0.310
Height	0.259
Width	4.563E-11
WidthAtBER	2.063E-11
HeightAtBER	0.075

85欧姆：眼高75mV

- 从插损回损上找原因



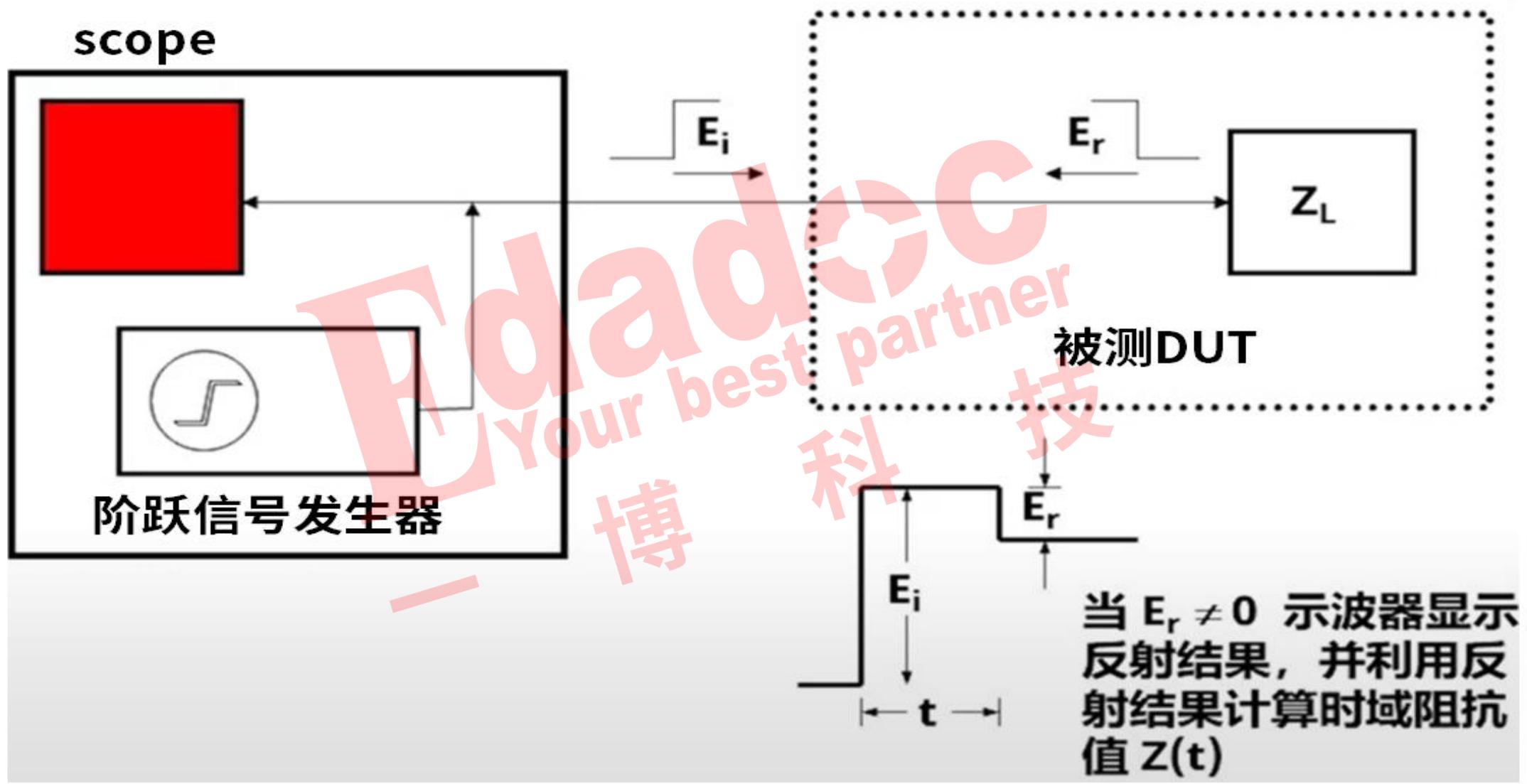
## PART 03

测出来的阻抗值一定是对的吗？

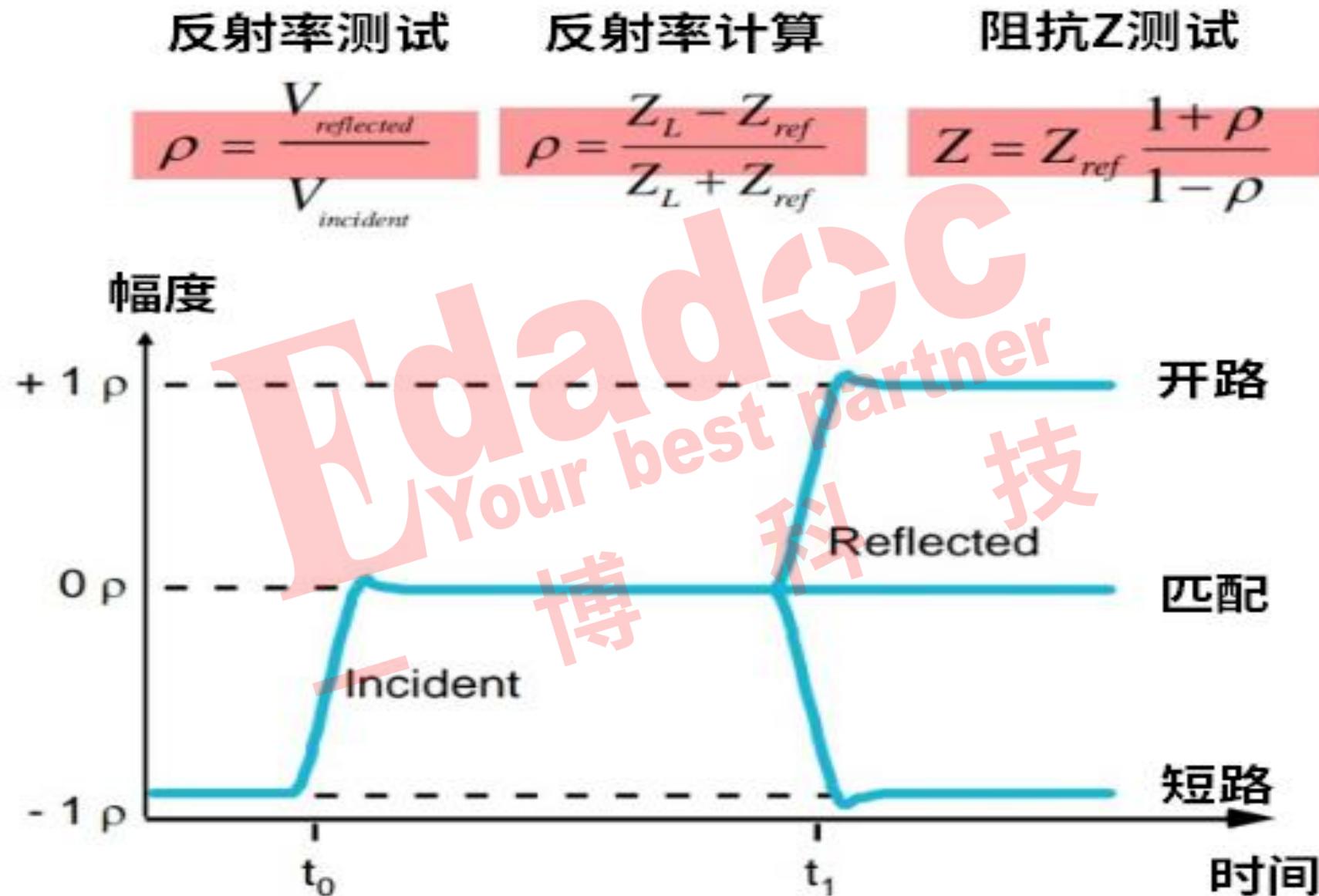


# 阻抗测试的基本原理

- 时域测试TDR阻抗

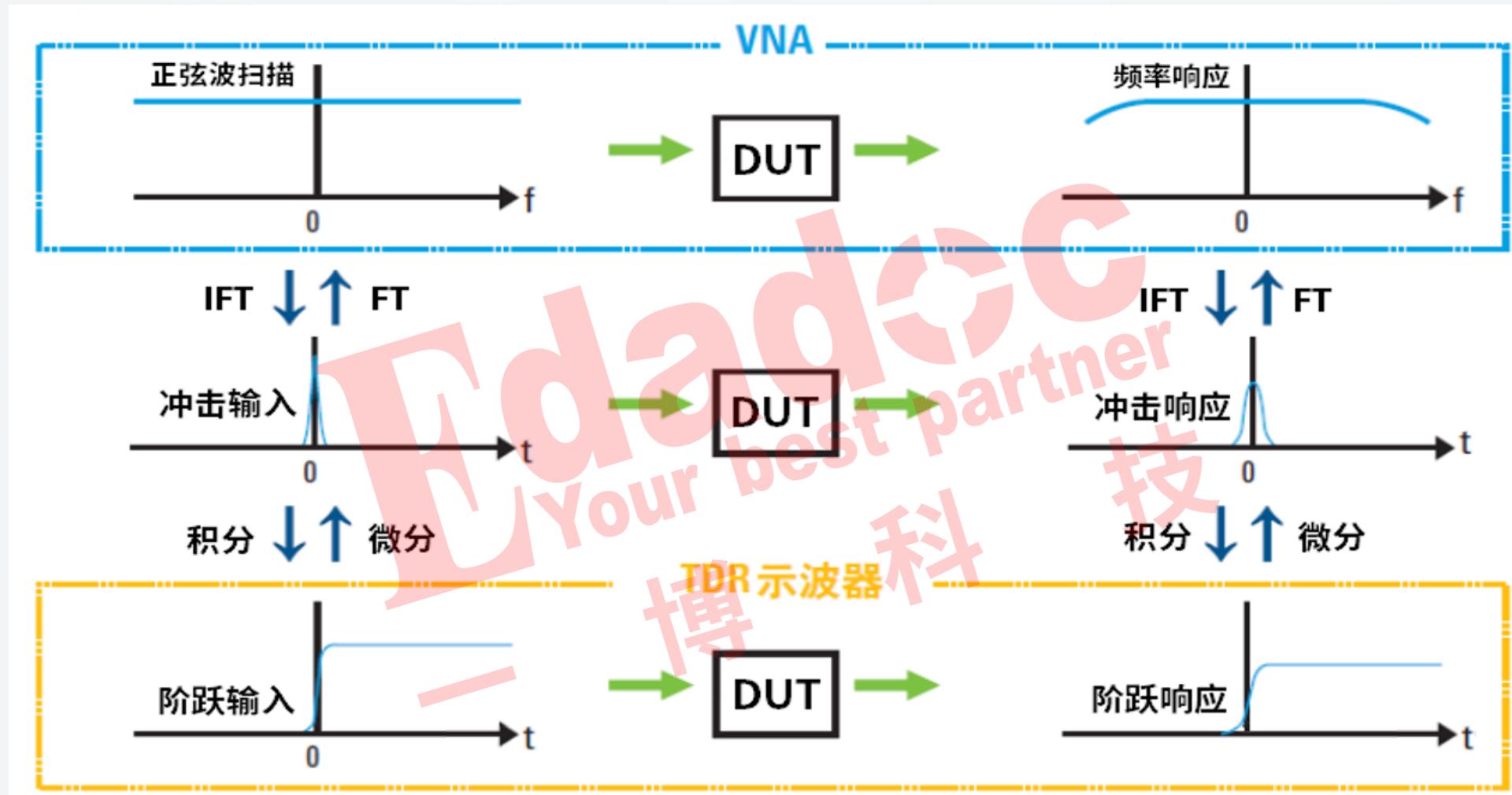


## • 时域测试TDR阻抗

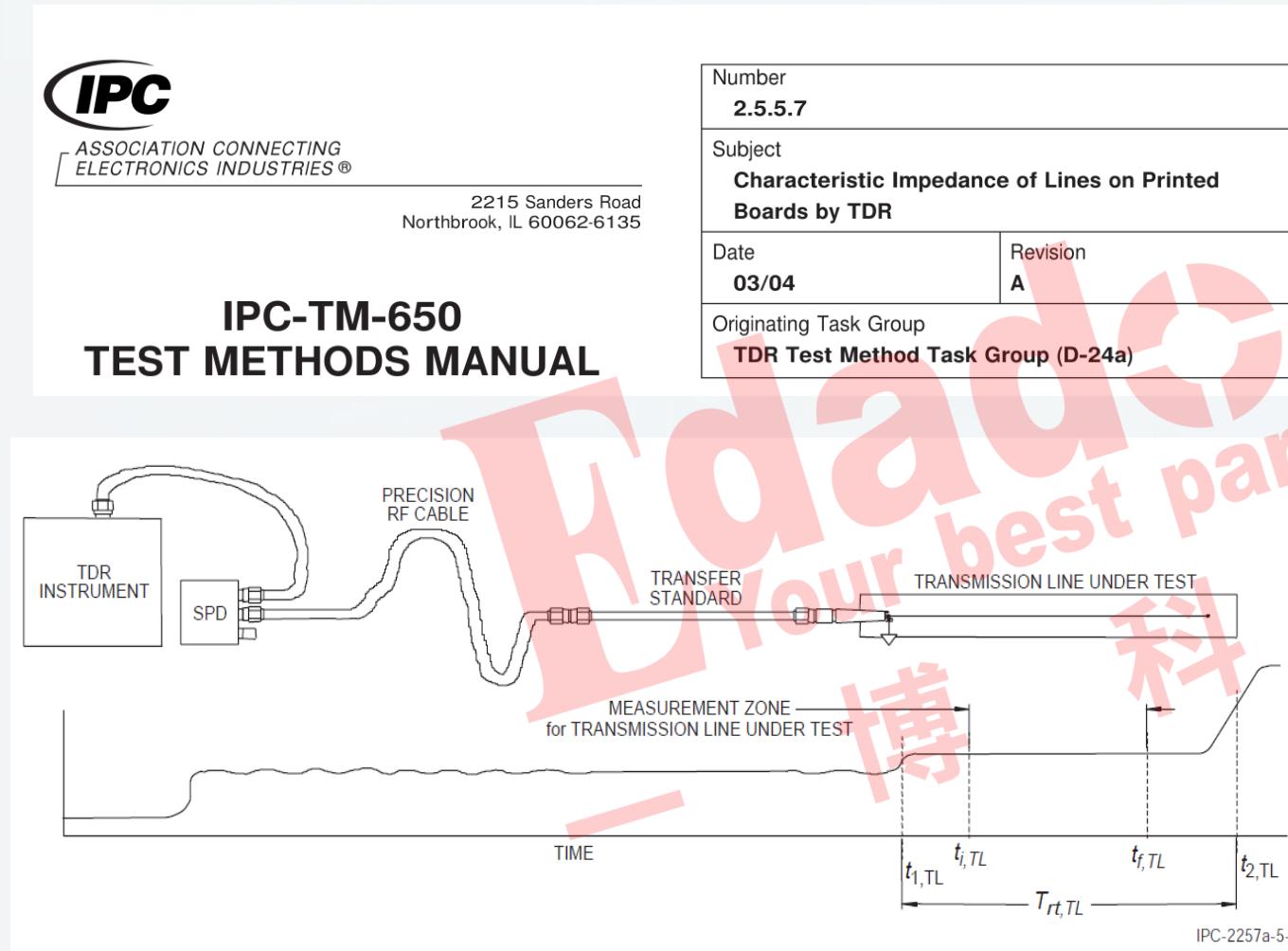


# 阻抗测试的基本原理

- 频域测试TDR阻抗---傅里叶逆变换



## • 出处



Step 4 – Determine the initial instant,  $t_{i,TL}$ , of measurement zone (see Figure 5-3) using:

$$t_{i,TL} = t_{1,TL} + x_{i\%} T_{R,TL}$$

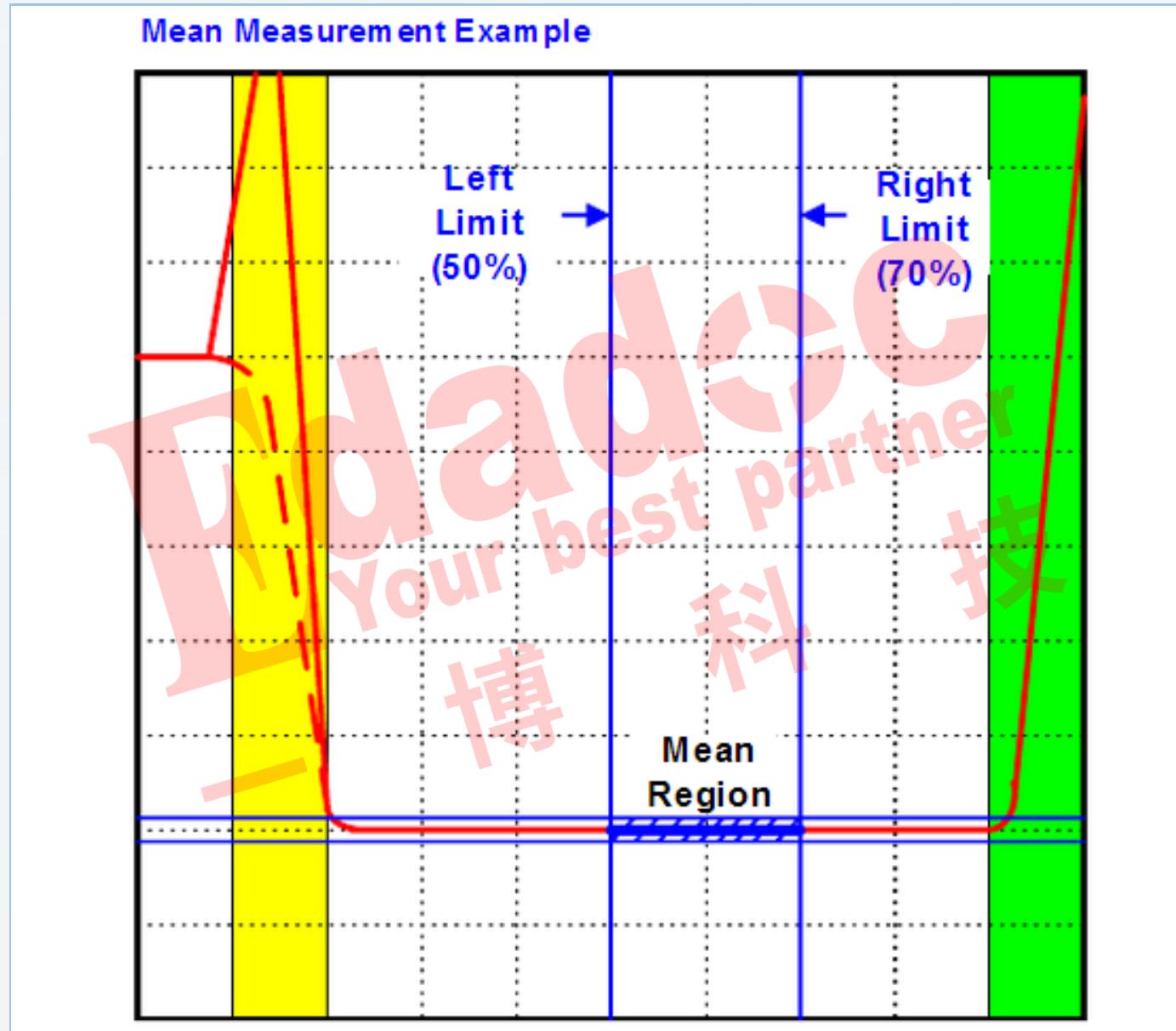
where  $x_{i\%}$  is the lower limit of the measurement zone and is 30 % unless otherwise specified by the user.

Step 5 – Determine final instant,  $t_{f,TL}$ , of measurement zone (see Figure 5-3) using:

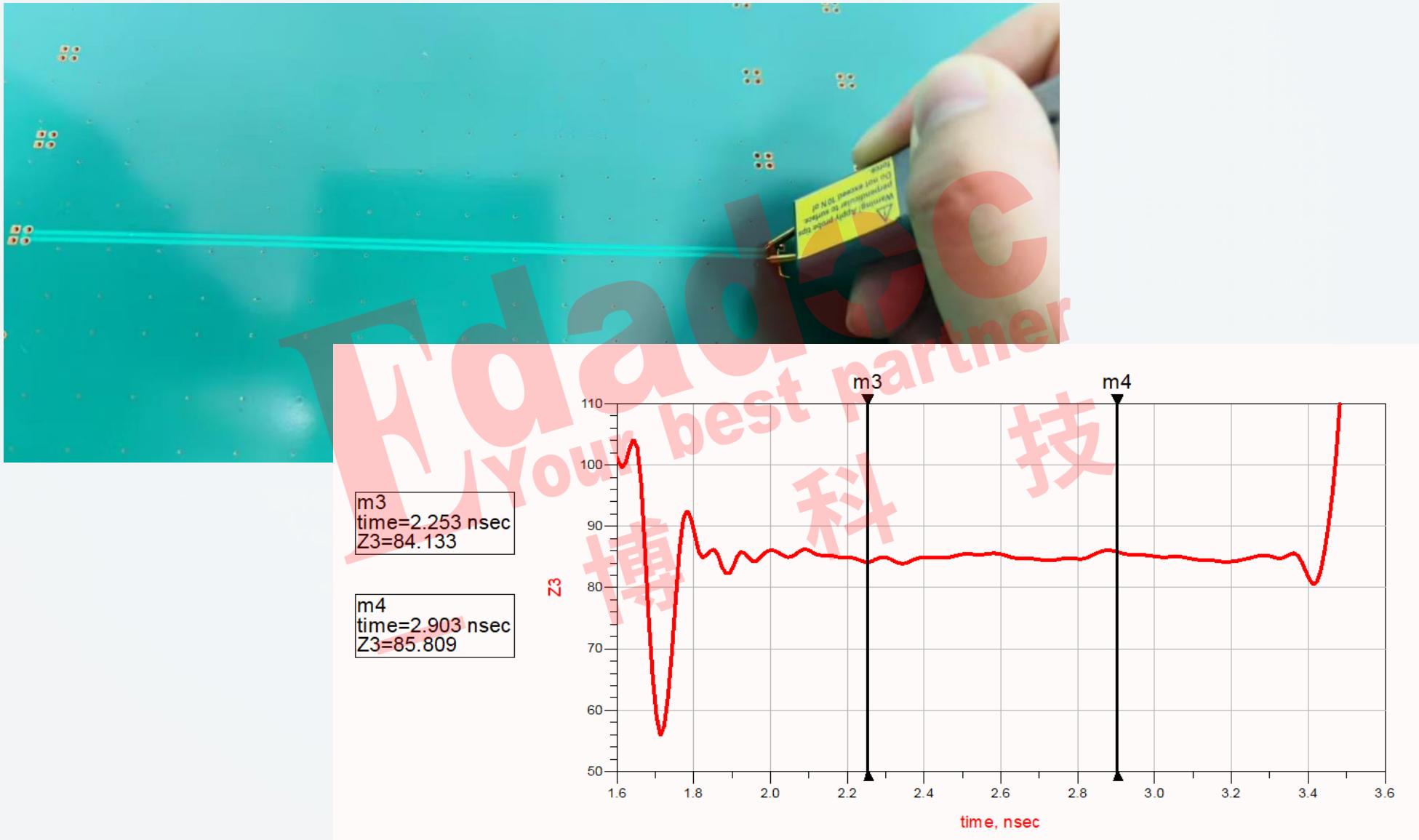
$$t_{f,TL} = t_{1,TL} + x_{f\%} T_{R,TL}$$

where  $x_{f\%}$  is the upper limit of the measurement zone and is 70 % unless otherwise specified by the user.

- Intel及多数板厂阻抗测试标准：50%-70%

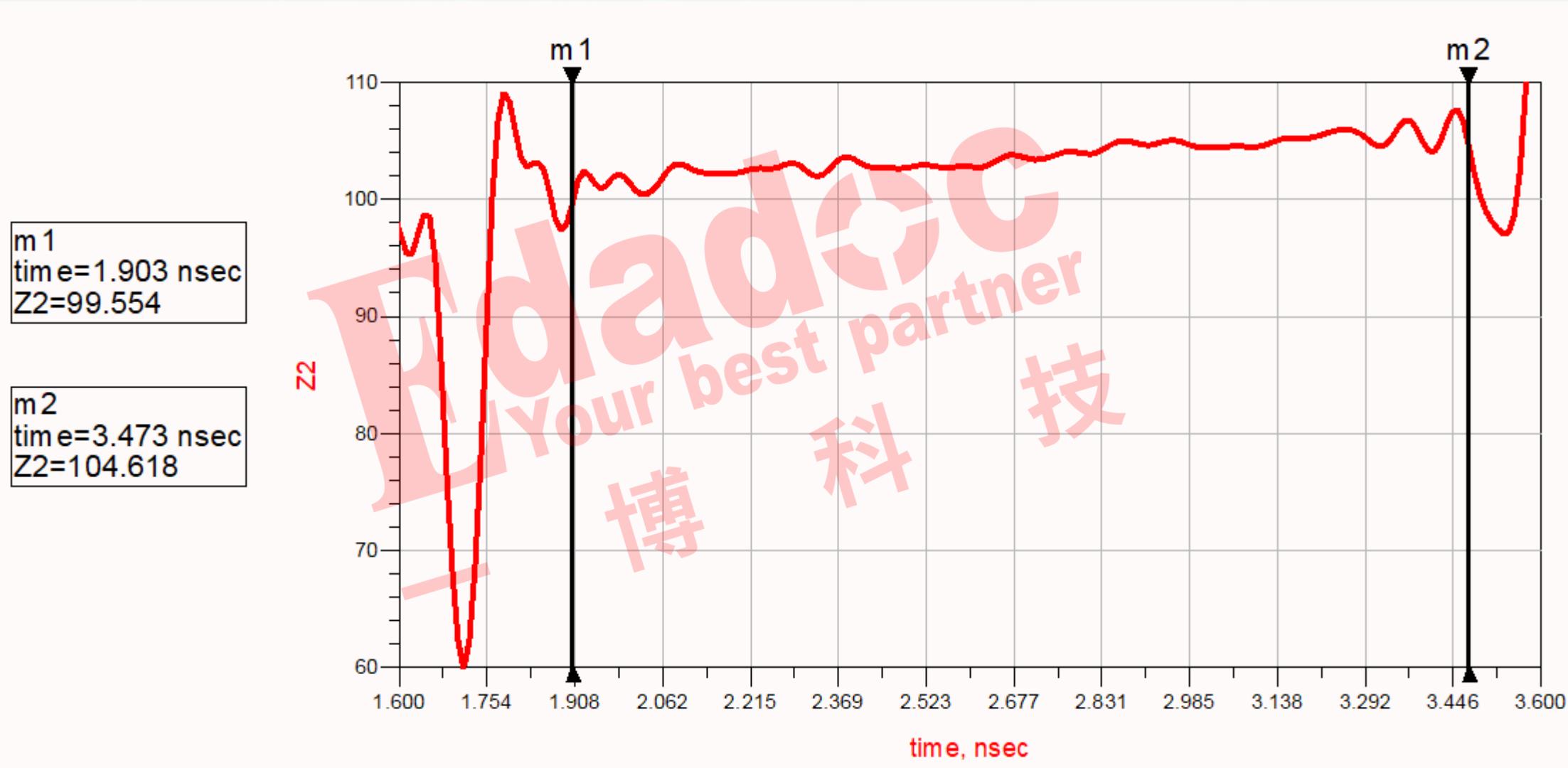


- 30%-70%区间的测试结果



## 阻抗上漂效应

- 阻抗上漂 100欧姆内层走线 30%-70%区间的阻抗
- 阻抗上漂 100欧姆的内层走线 起始到末端，相差5.1欧姆

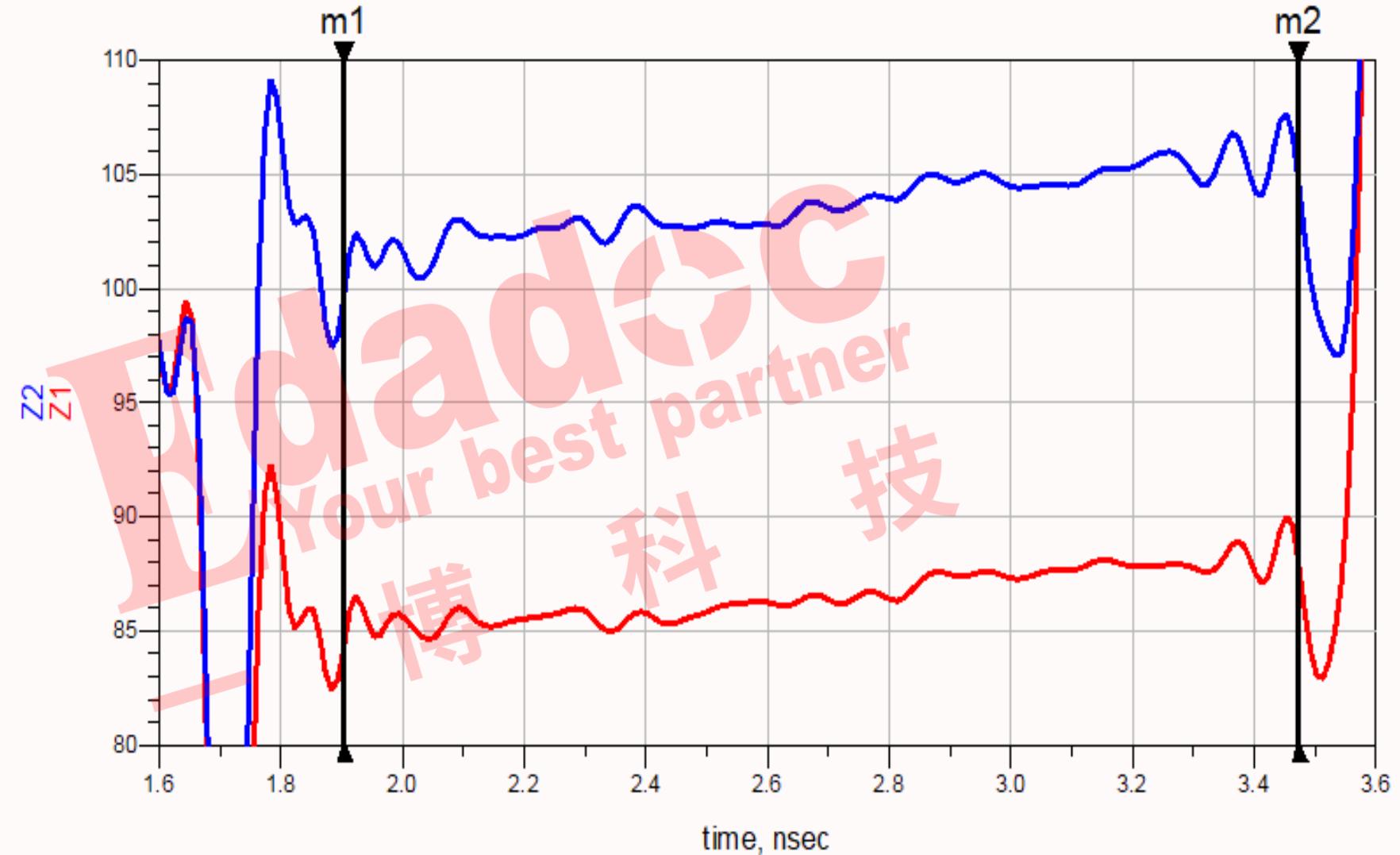


# 阻抗上漂效应

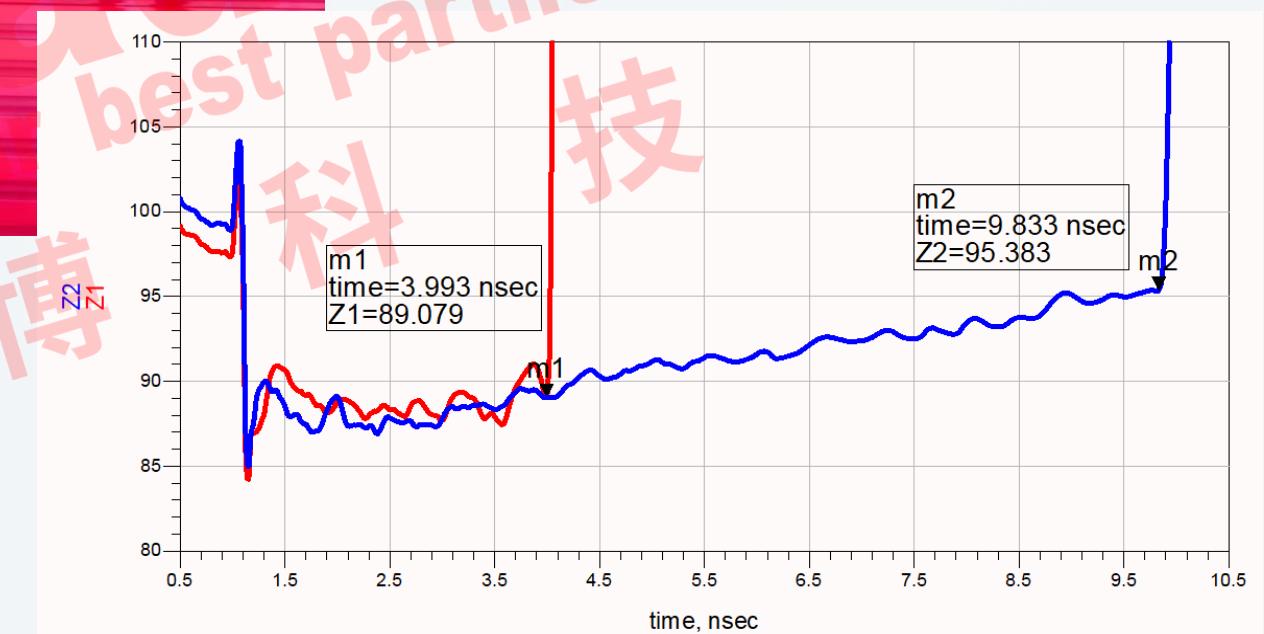
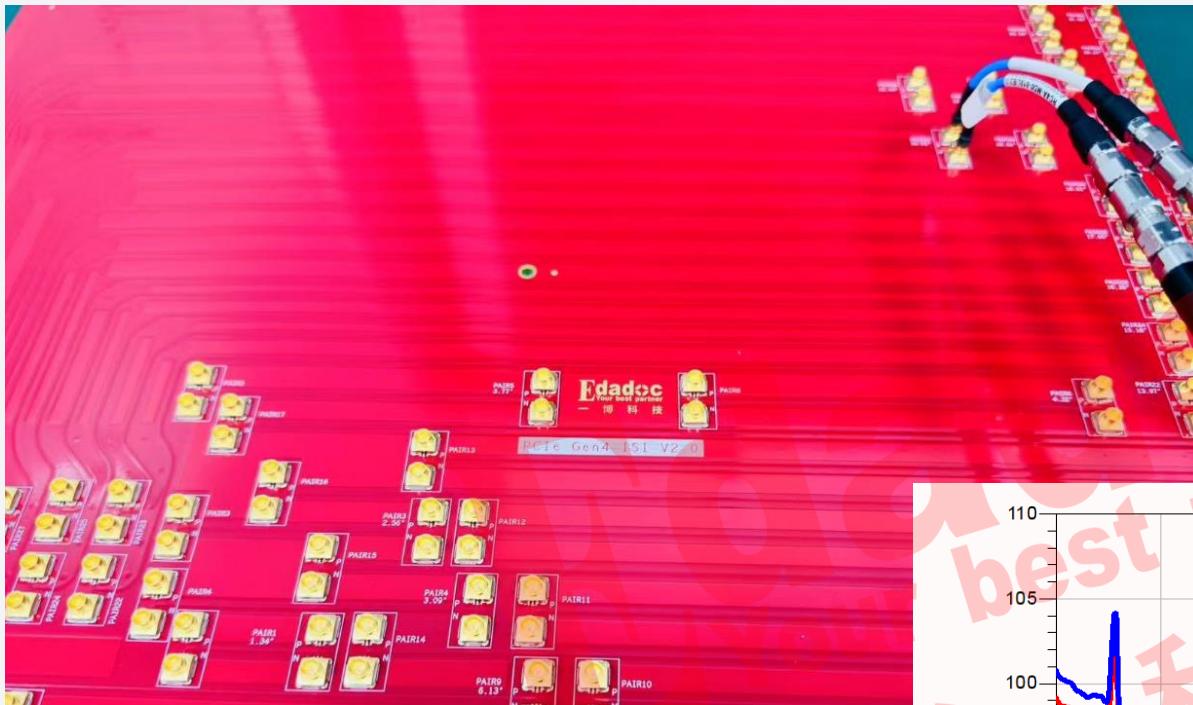
- 阻抗上漂 对比 85欧姆阻抗上漂3.8ohm, 100欧姆阻抗上漂5.1ohm。

m1  
time=1.903 nsec  
Z1=84.213  
Z2=99.554

m2  
time=3.473 nsec  
Z1=87.982  
Z2=104.618

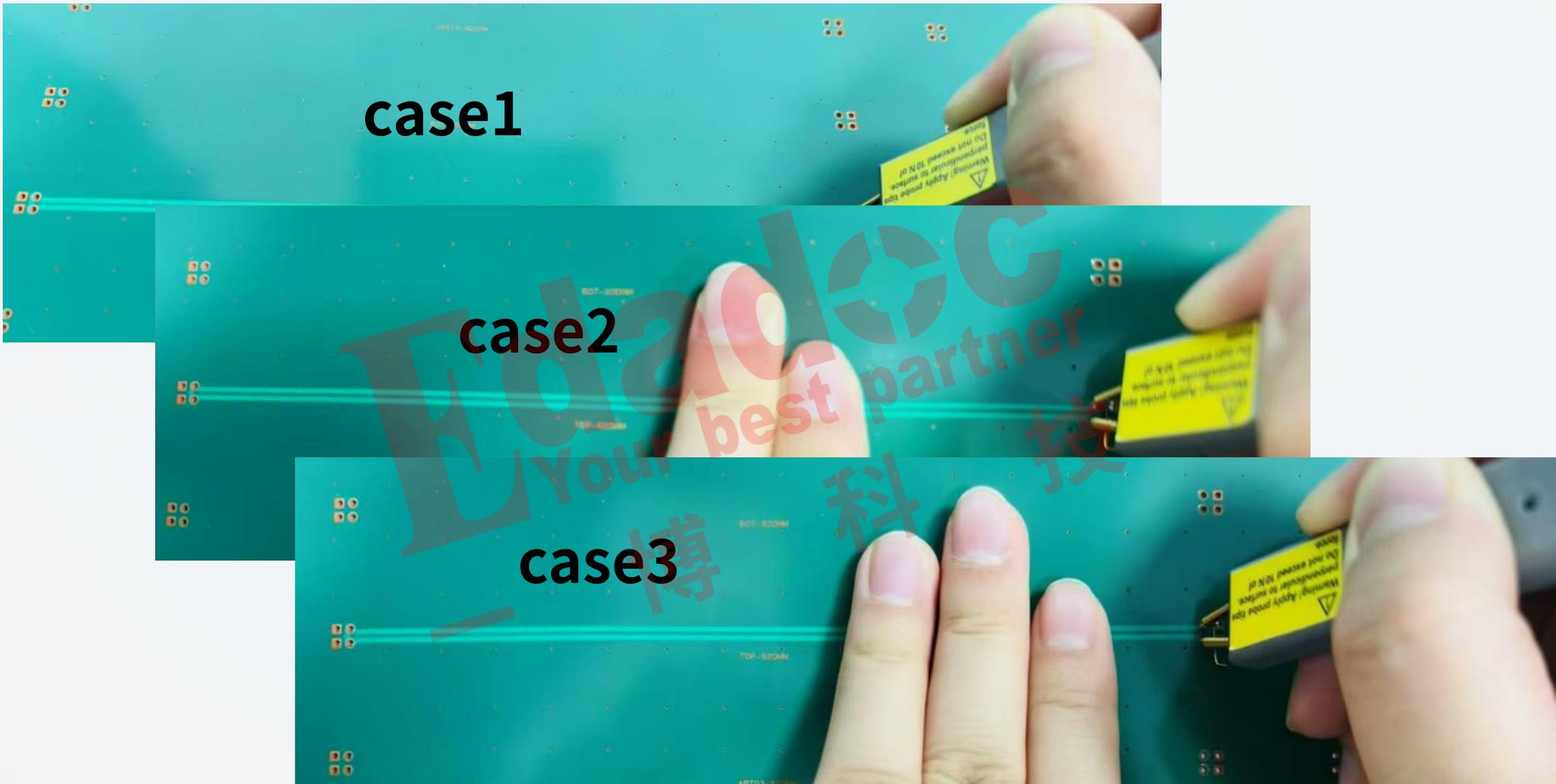


- 不同长度的通道对比，上漂量之间的差异。

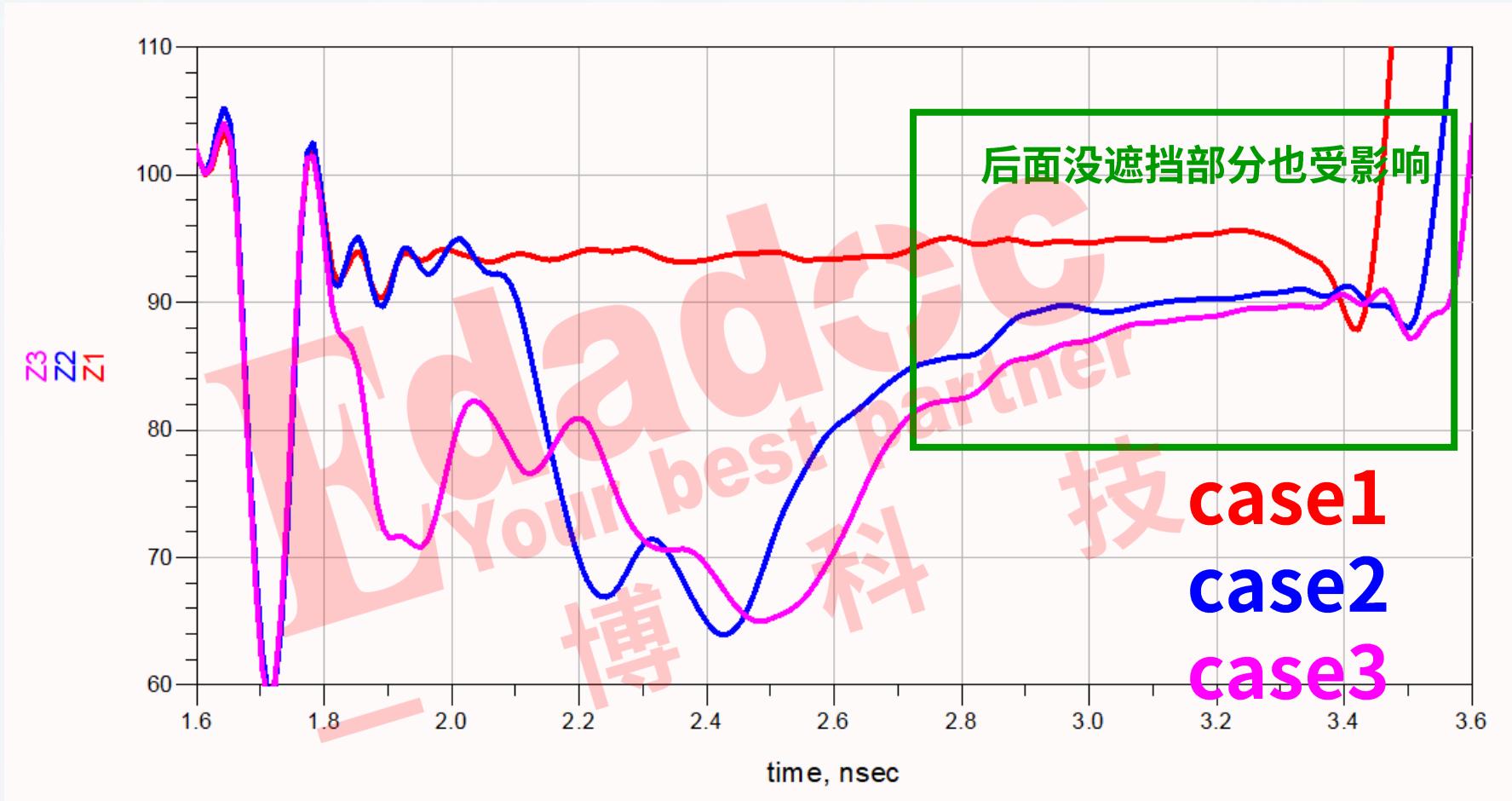


# 阻抗的遮挡效应

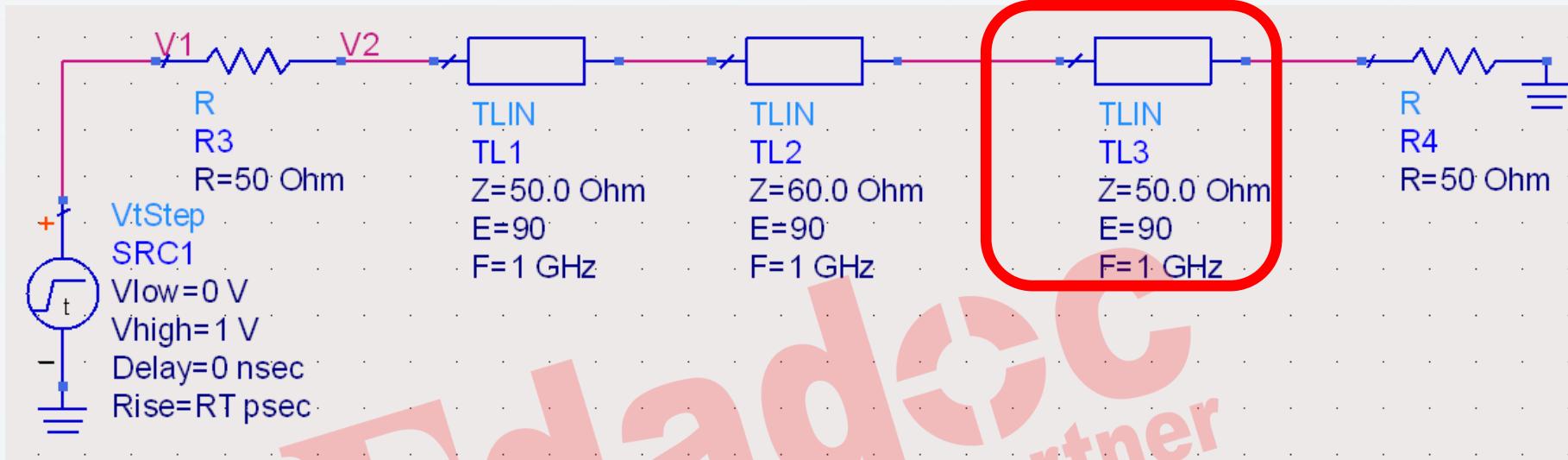
- 一个小实验



# 阻抗的遮挡效应



# 阻抗的遮挡效应的理论验证



第一次反射  $1/11$ , 剩下  $10/11$  传输

第二次反射系数  $(50-60)/(60+50)$

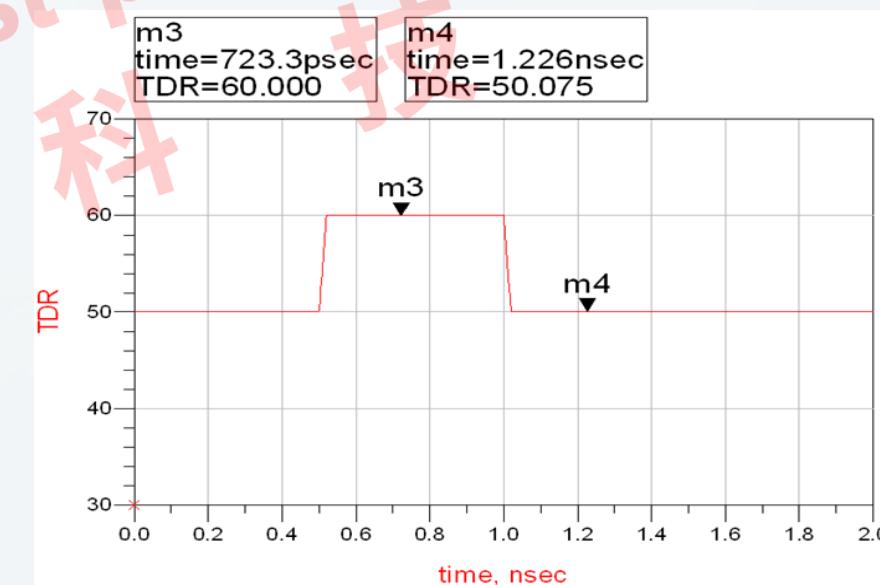
反射  $10/11$  的  $-1/11$ , 也就是  $-10/121$

而这个经过第一次阻抗变化的地方时, 又会反射掉  $-10/121$  的  $-1/11$ , 传输  $12/11$

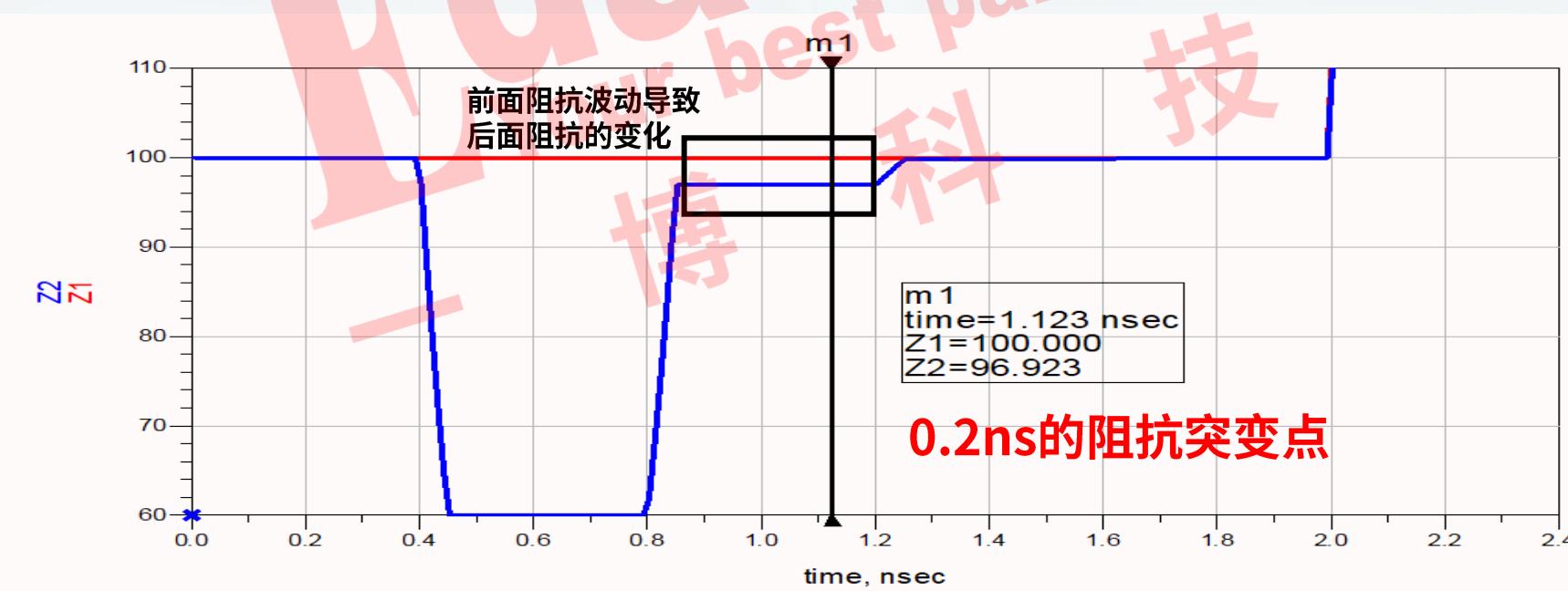
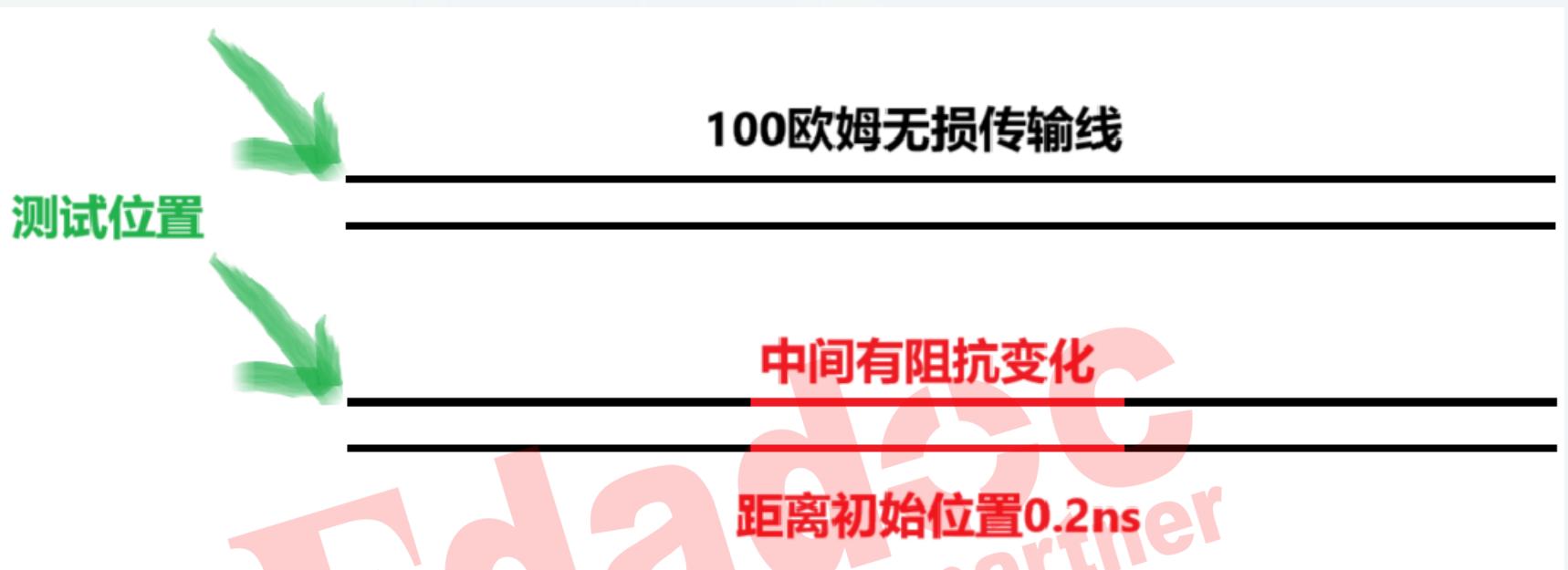
实际再传向源端的等于  $-10/121 * 12/11 = -120/1331$

这时候  $V2$  变化了  $1/11 - 120/1331 = 1/1331$

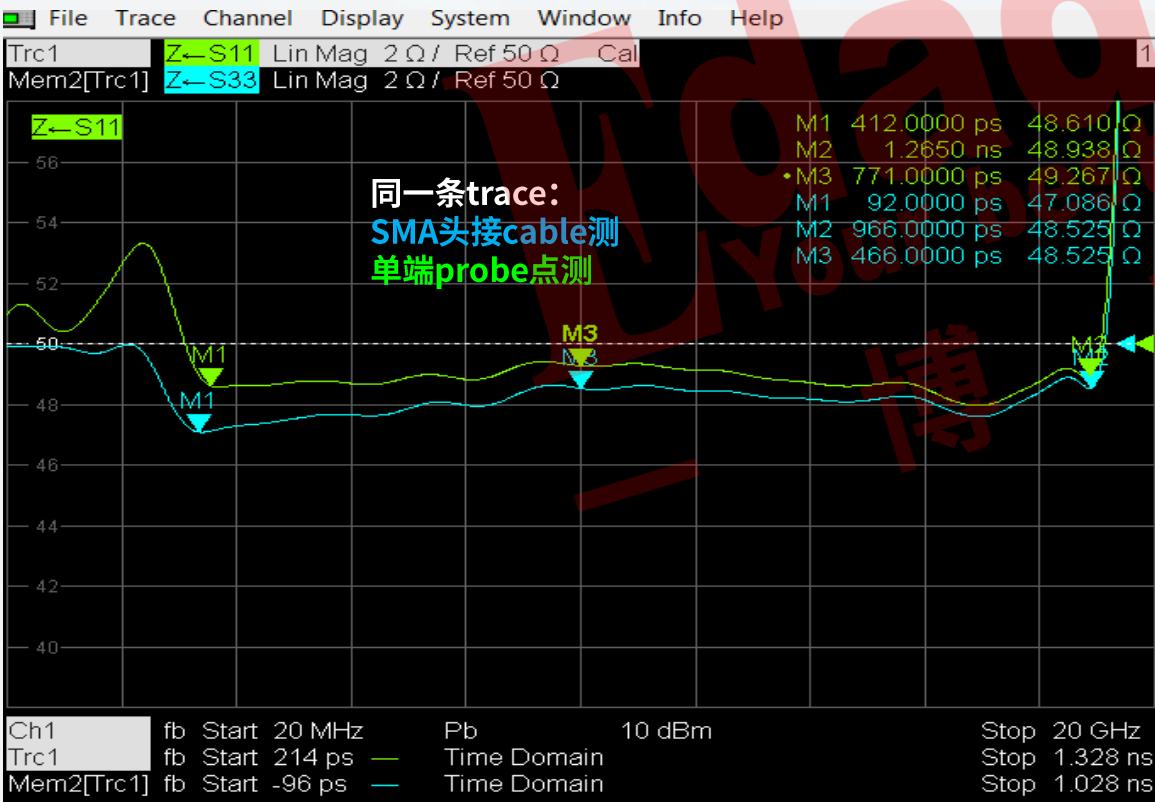
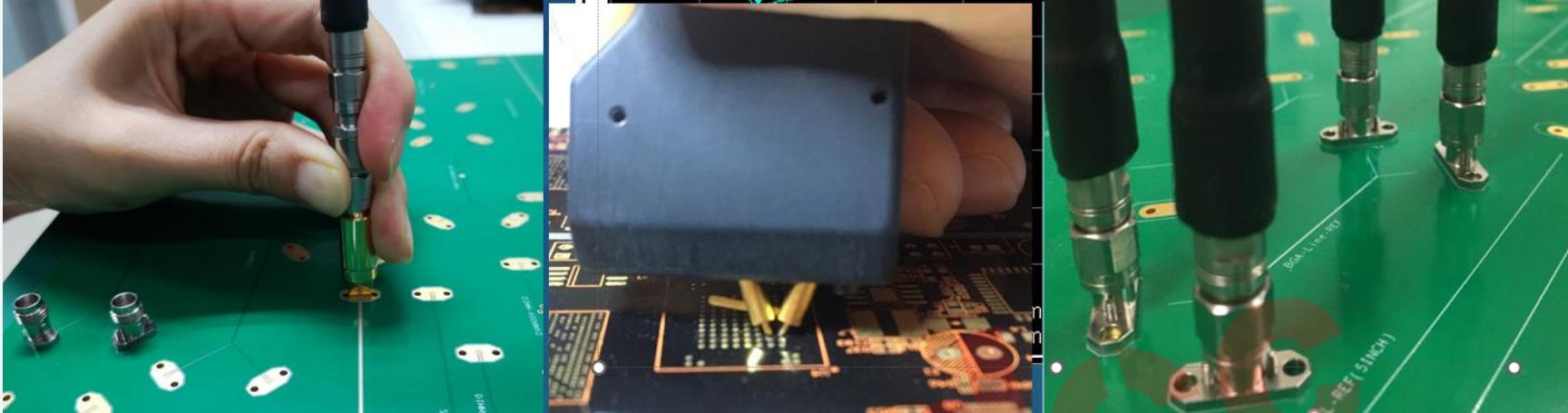
所以本来应该是 50 欧姆的阻抗, 变成了  $50 * 1332 / 1330 = 50.075$



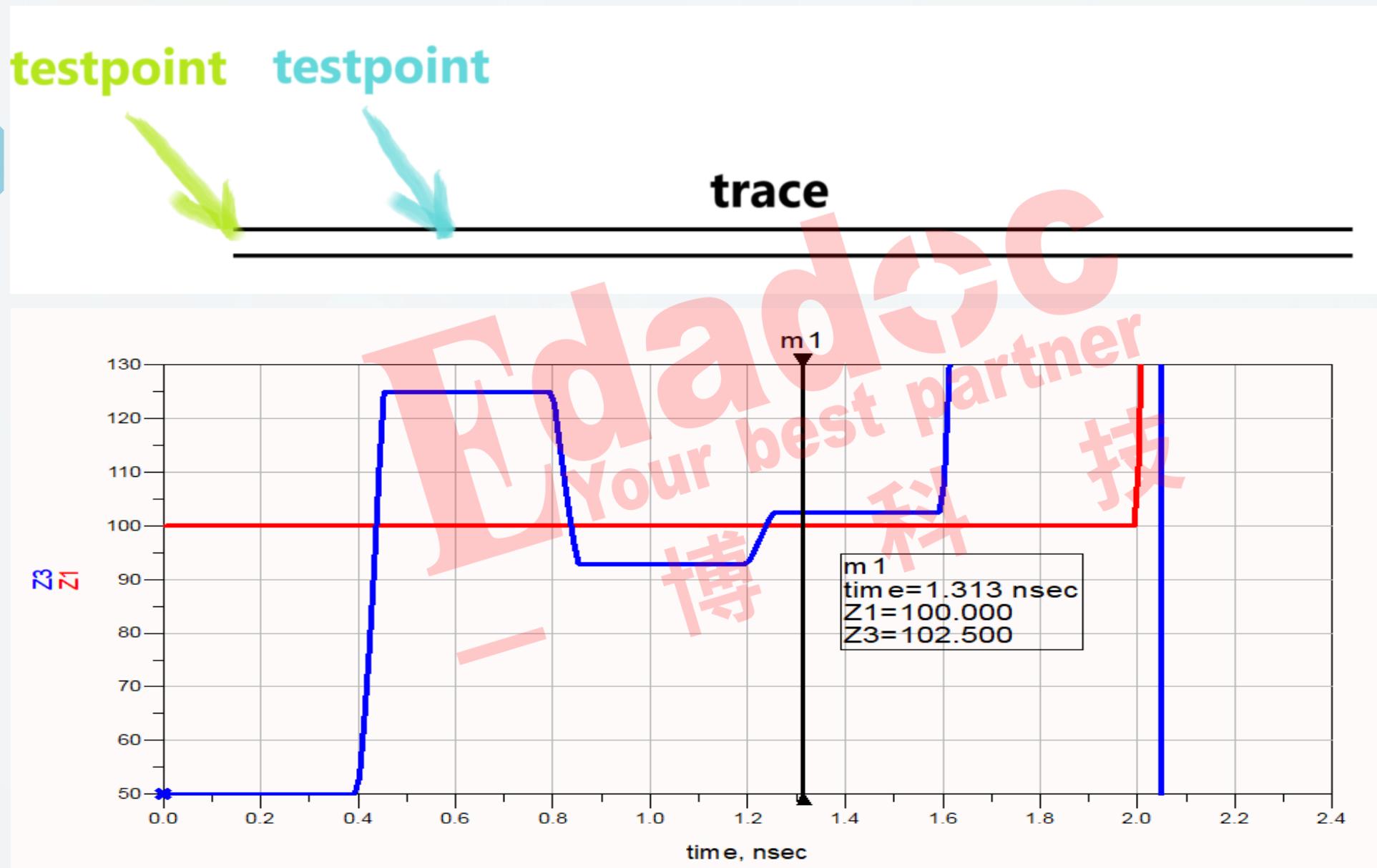
# 阻抗的遮挡效应仿真验证



# 点测探头也是一种遮挡效应



- 如果不在发送端测试，在链路的中间测试……



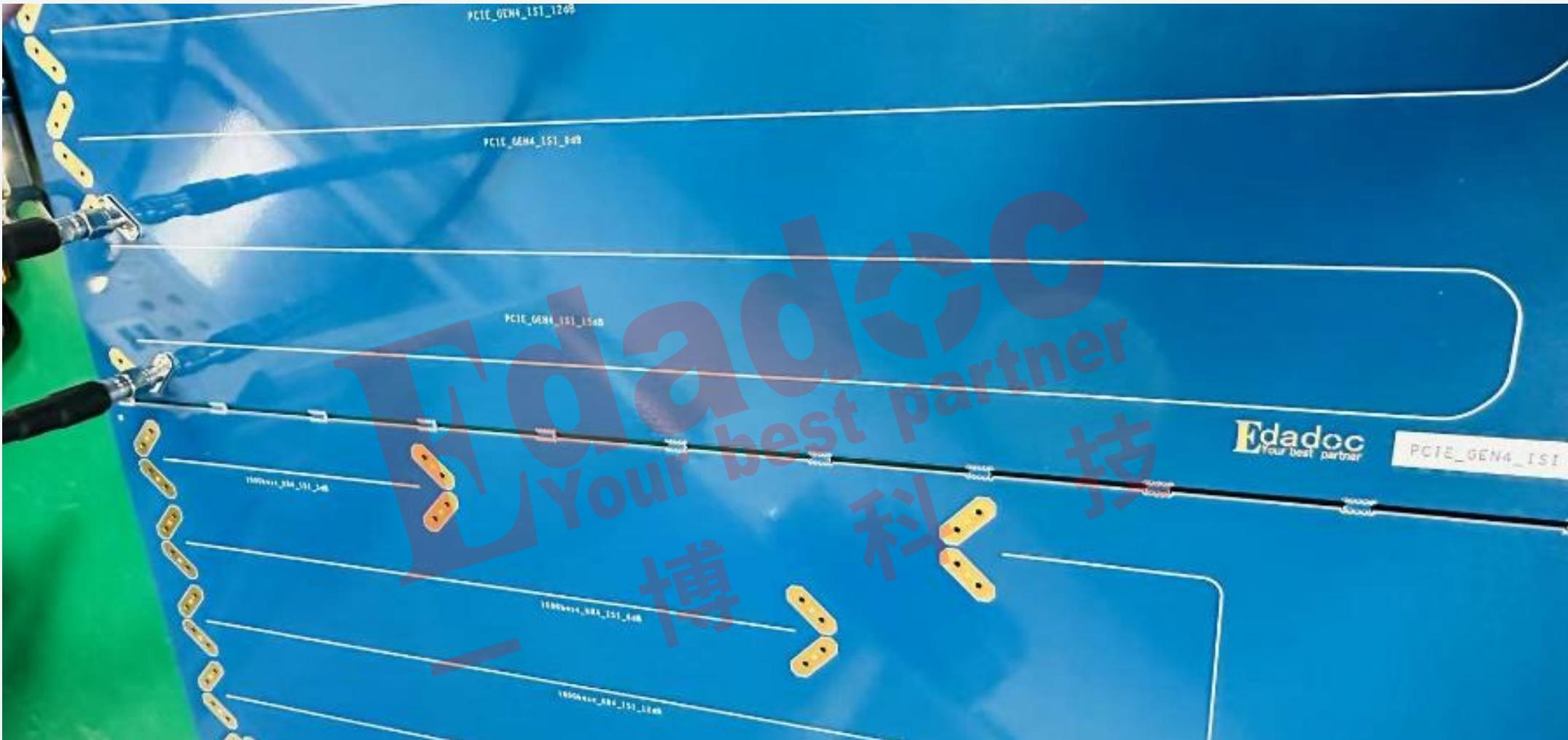
# 另外一种遮挡效应

- 实测也是这样的现象。。

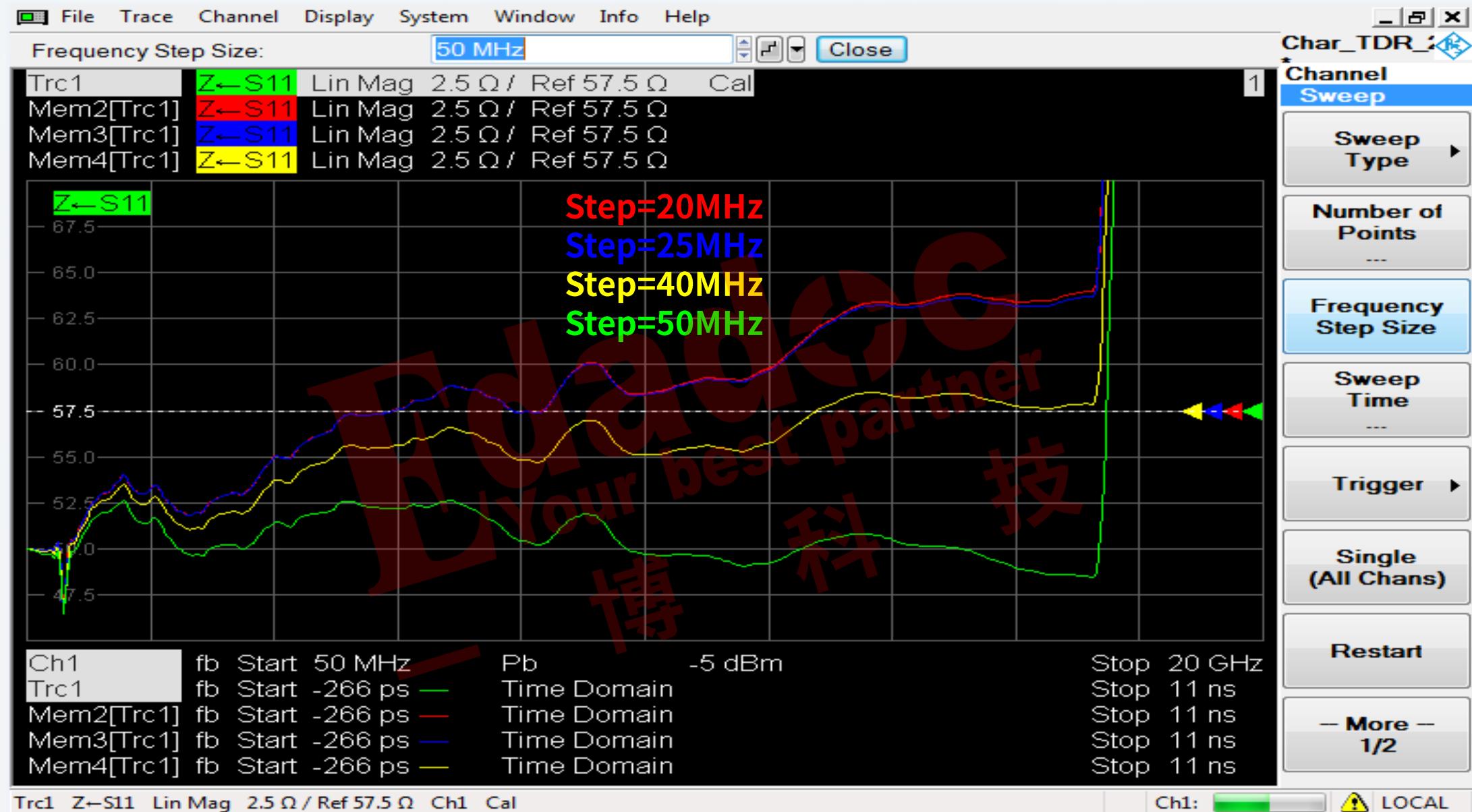


# Step会影响阻抗?

- 网络分析仪设置频率间隔step也会影响测出来的阻抗? ? ?



# Step 会影响阻抗?



# 阻抗的不同测试仪器之间的偏差

- 用不同测试仪器对号称阻抗很理想的空气棒进行阻抗测试



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- 用不同测试仪器对号称阻抗很理想的空气棒进行阻抗测试



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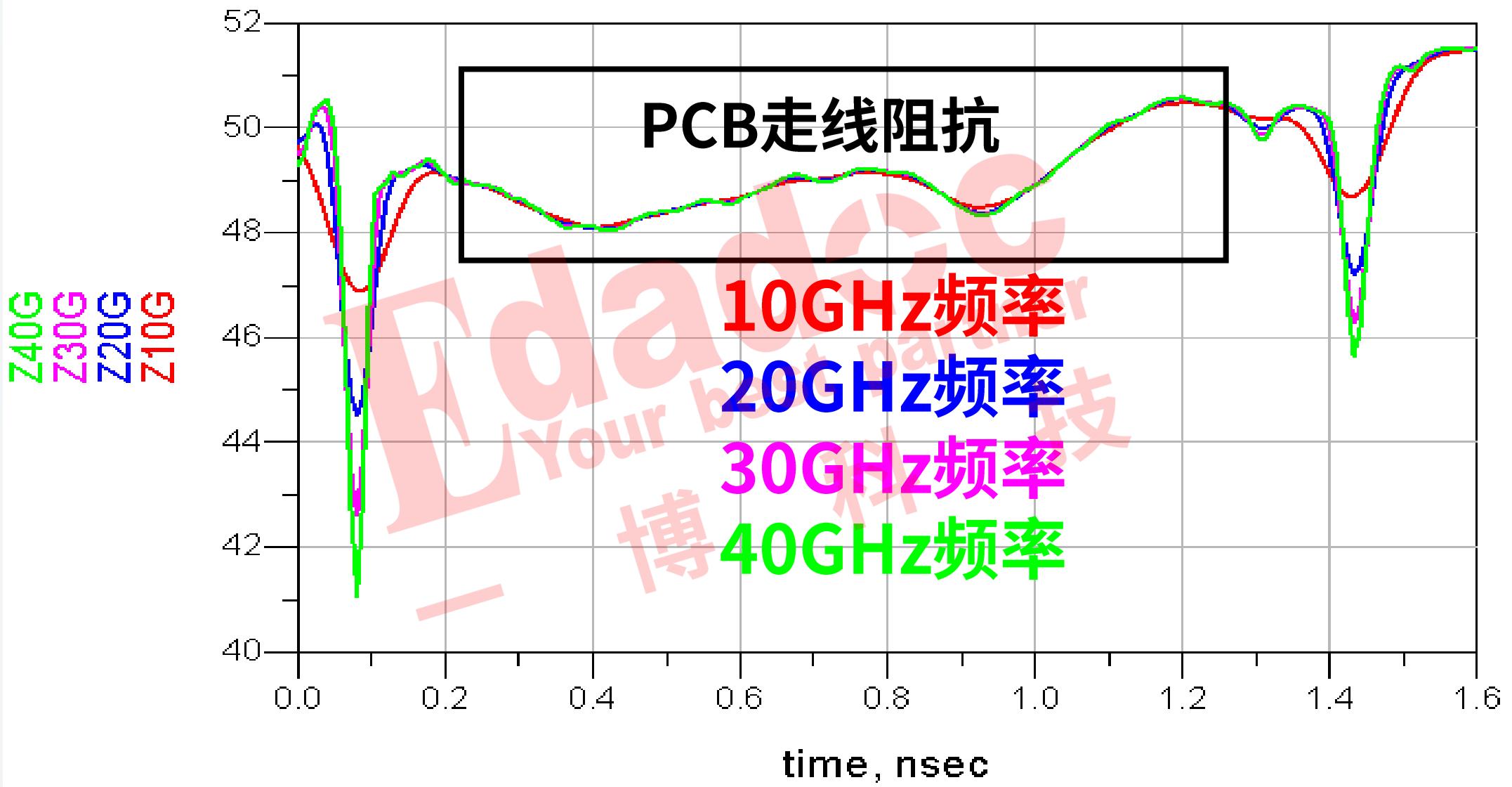


- 一定要用到40GHz以上的网络分析仪来测走线的阻抗？



测走线阻抗需要用很高的带宽吗？

- 一定要用到40GHz以上的网络分析仪来测走线的阻抗？

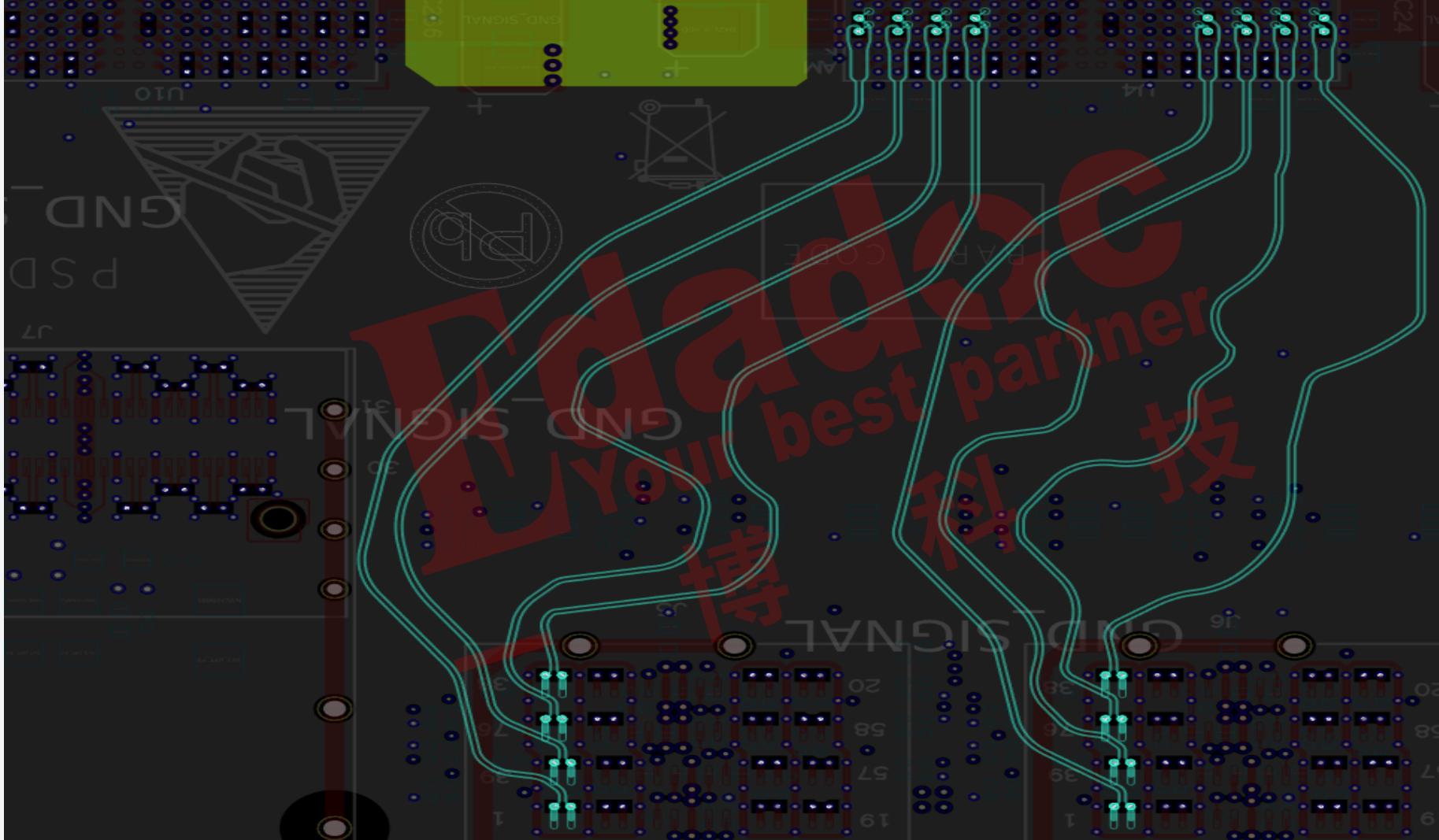


## PART 04

# 超高速对阻抗设计和加工同时考验

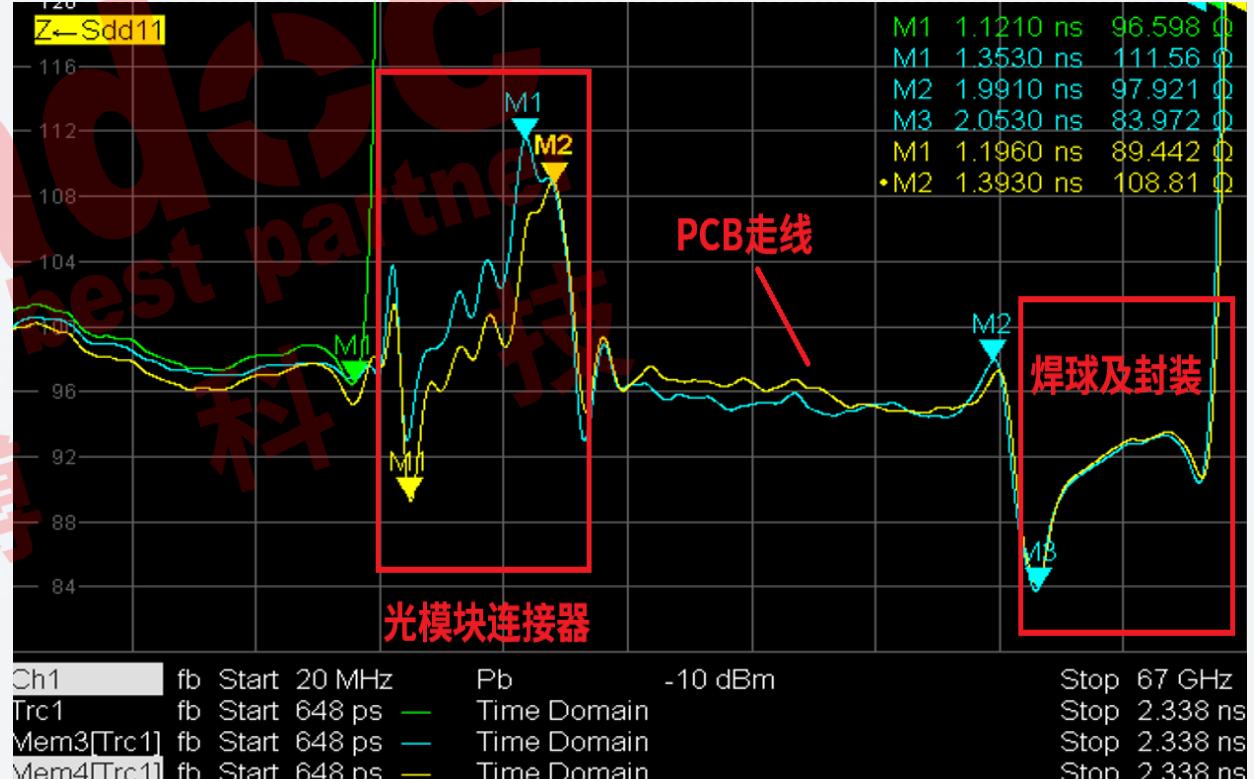
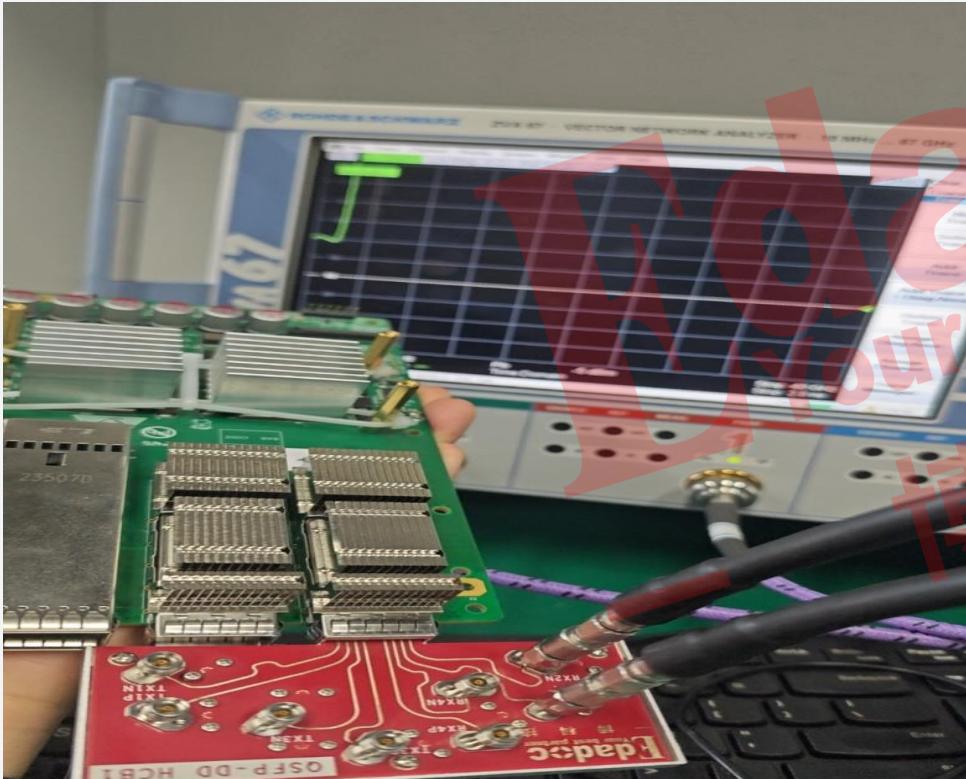


- 第一版客户反馈功能ok，但希望回环的误码率（当前1E-7）再降低一点。
- PCB链路如下



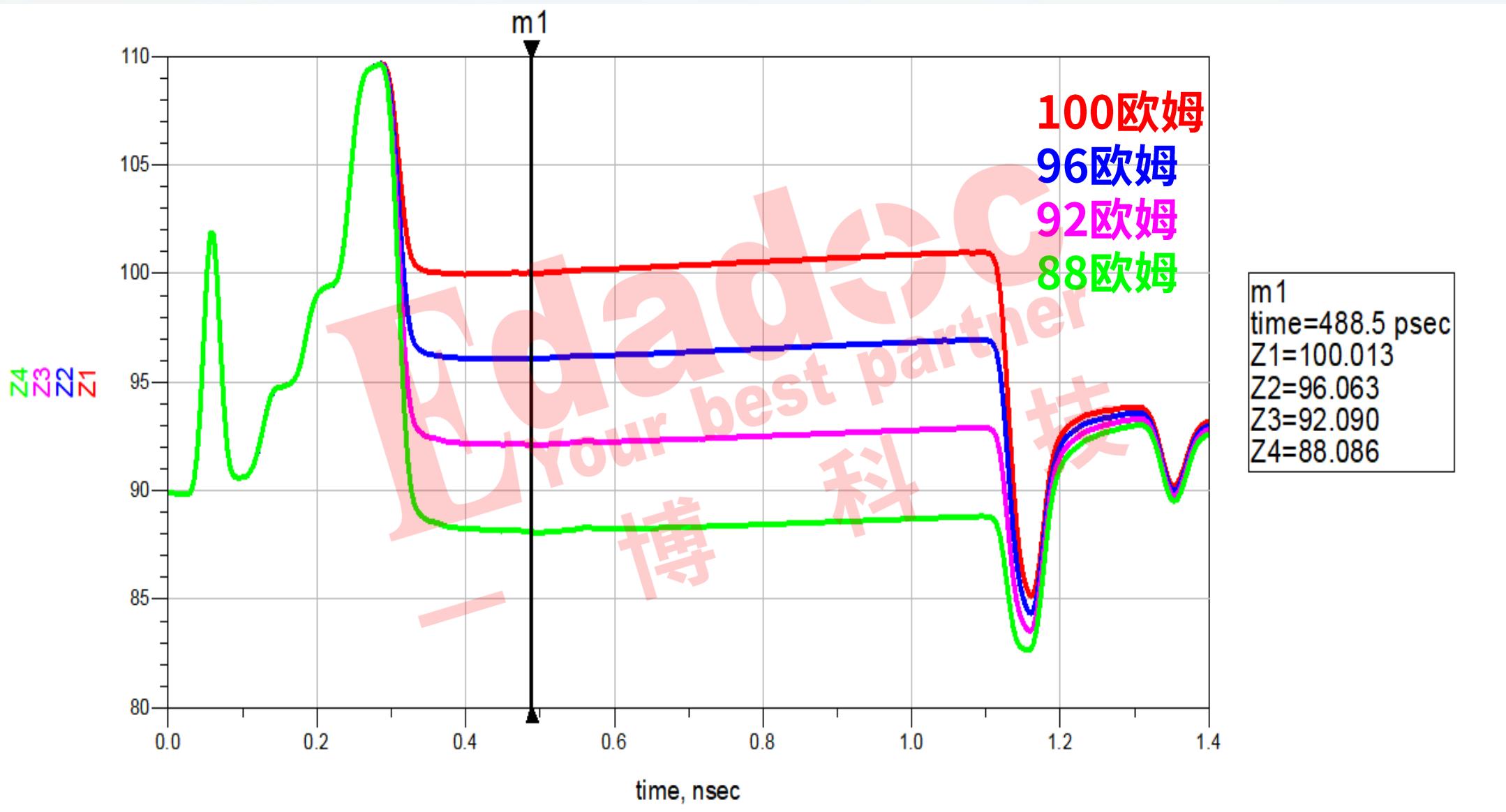
# 第一版加工后的阻抗测试

- 该版本的测试链路示意图及阻抗测试结果如下，从HCB夹具到芯片



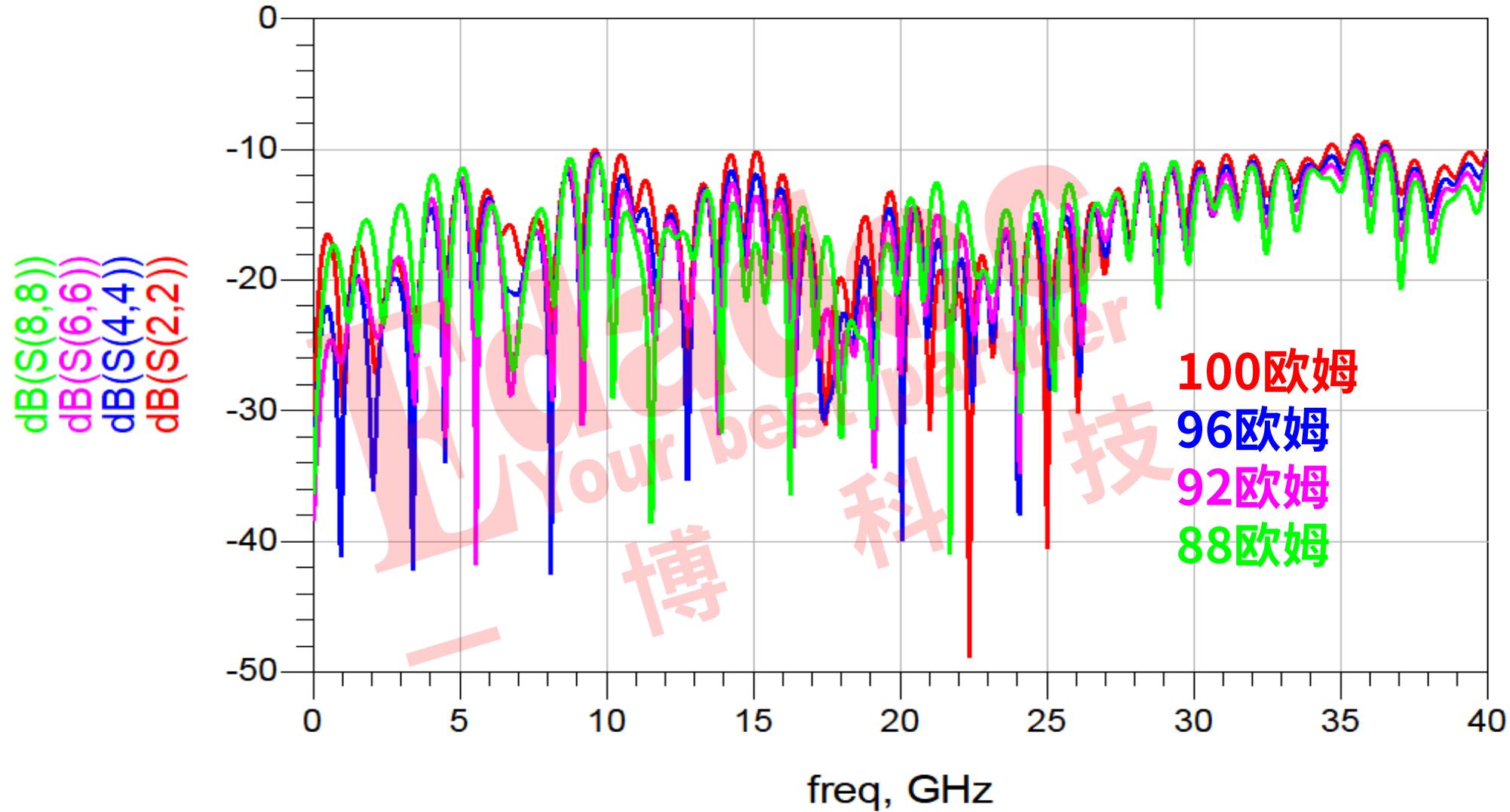
# 建模仿真不同走线阻抗的影响

- 建模仿真不同走线阻抗的影响



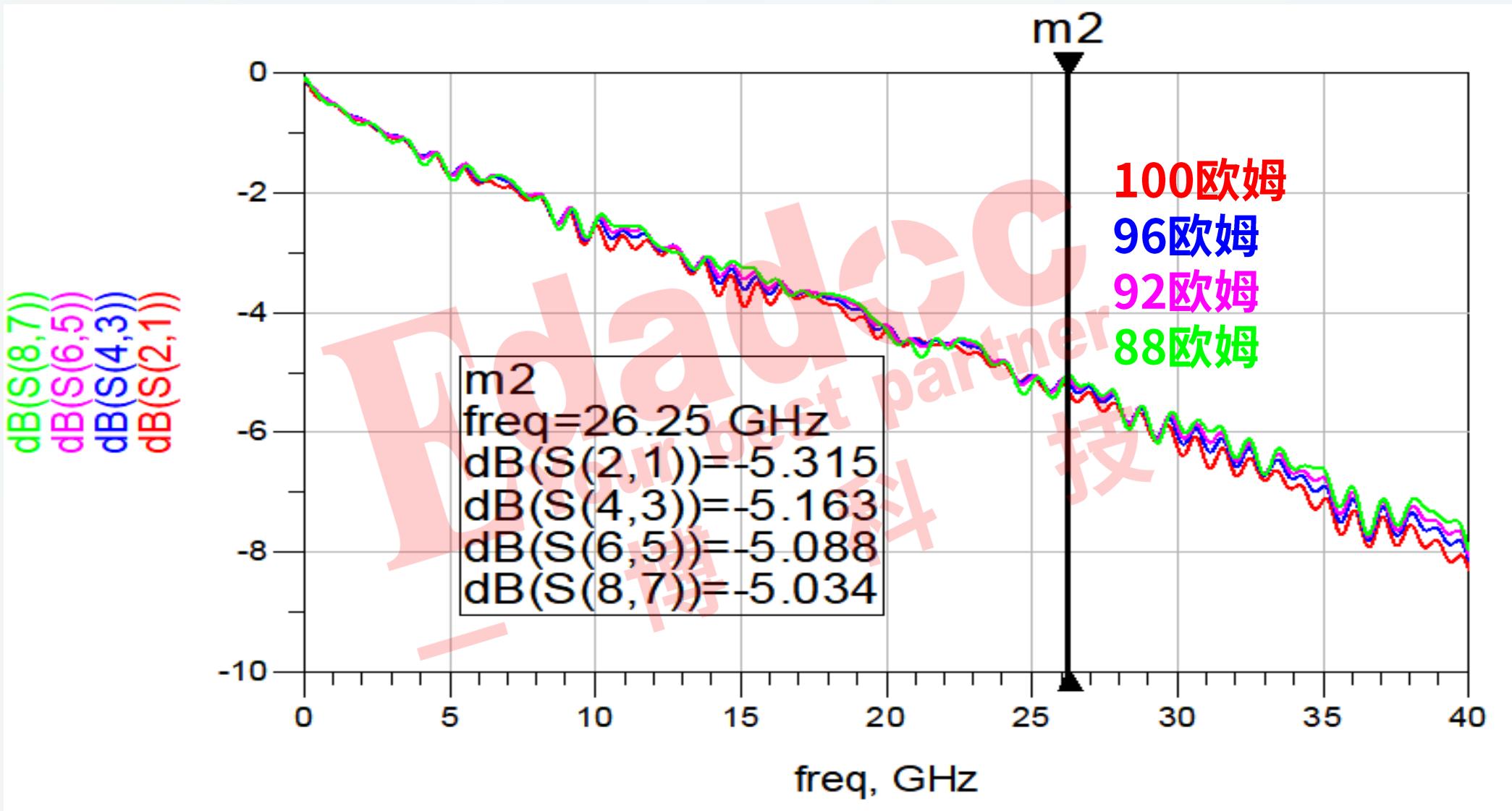
# 建模仿真不同走线阻抗的影响

- 回损仿真对比



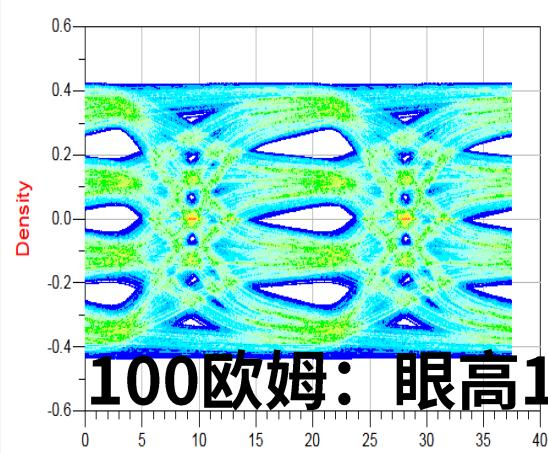
# 建模仿真不同走线阻抗的影响

- 插损仿真对比

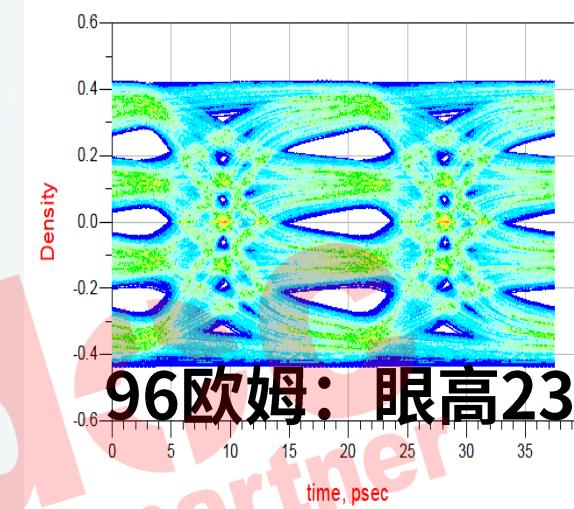


# 建模仿真不同走线阻抗的影响

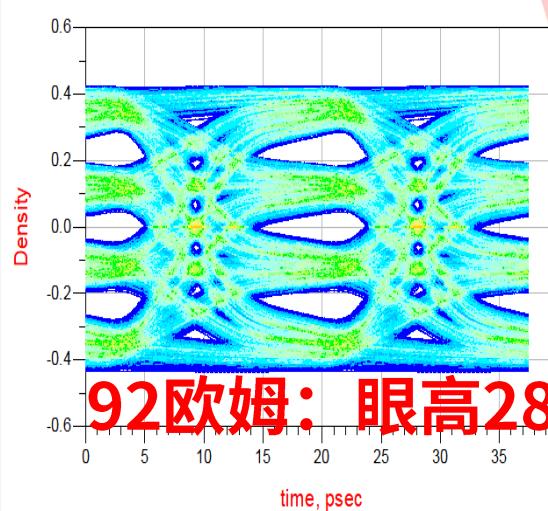
- 100ohm-96ohm-92ohm-88ohm传输线眼图仿真对比



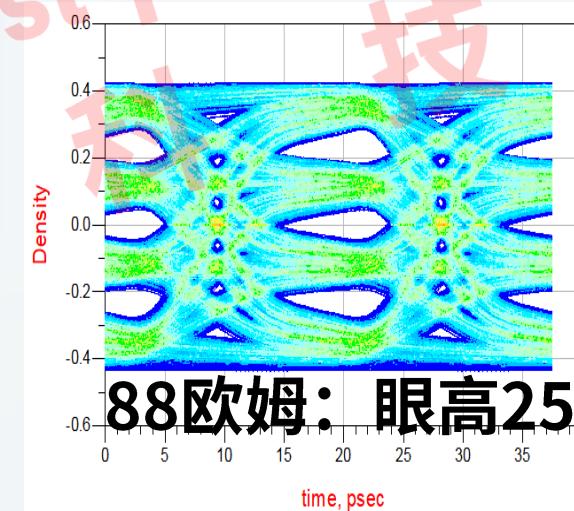
measurement	Summary
WidthAtBER0	1.596E-12
WidthAtBER1	2.722E-12
WidthAtBER2	5.820E-12
HeightAtBER0	0.018
HeightAtBER1	0.030
HeightAtBER2	0.066
Tmid	1.924E-11
Vlow	-0.589
Vmid	-0.544
Vupp	0.047
Hlow	1.877E-13
Hmid	9.387E-14
Hupp	5.069E-12
AVlow	0.231
AVmid	0.233
AVupp	0.222



measurement	Summary
WidthAtBER0	3.004E-12
WidthAtBER1	3.379E-12
WidthAtBER2	5.820E-12
HeightAtBER0	0.023
HeightAtBER1	0.037
HeightAtBER2	0.073
Tmid	1.924E-11
Vlow	0.014
Vmid	-0.102
Vupp	0.050
Hlow	2.910E-12
Hmid	1.877E-13
Hupp	5.351E-12
AVlow	0.232
AVmid	0.231
AVupp	0.223



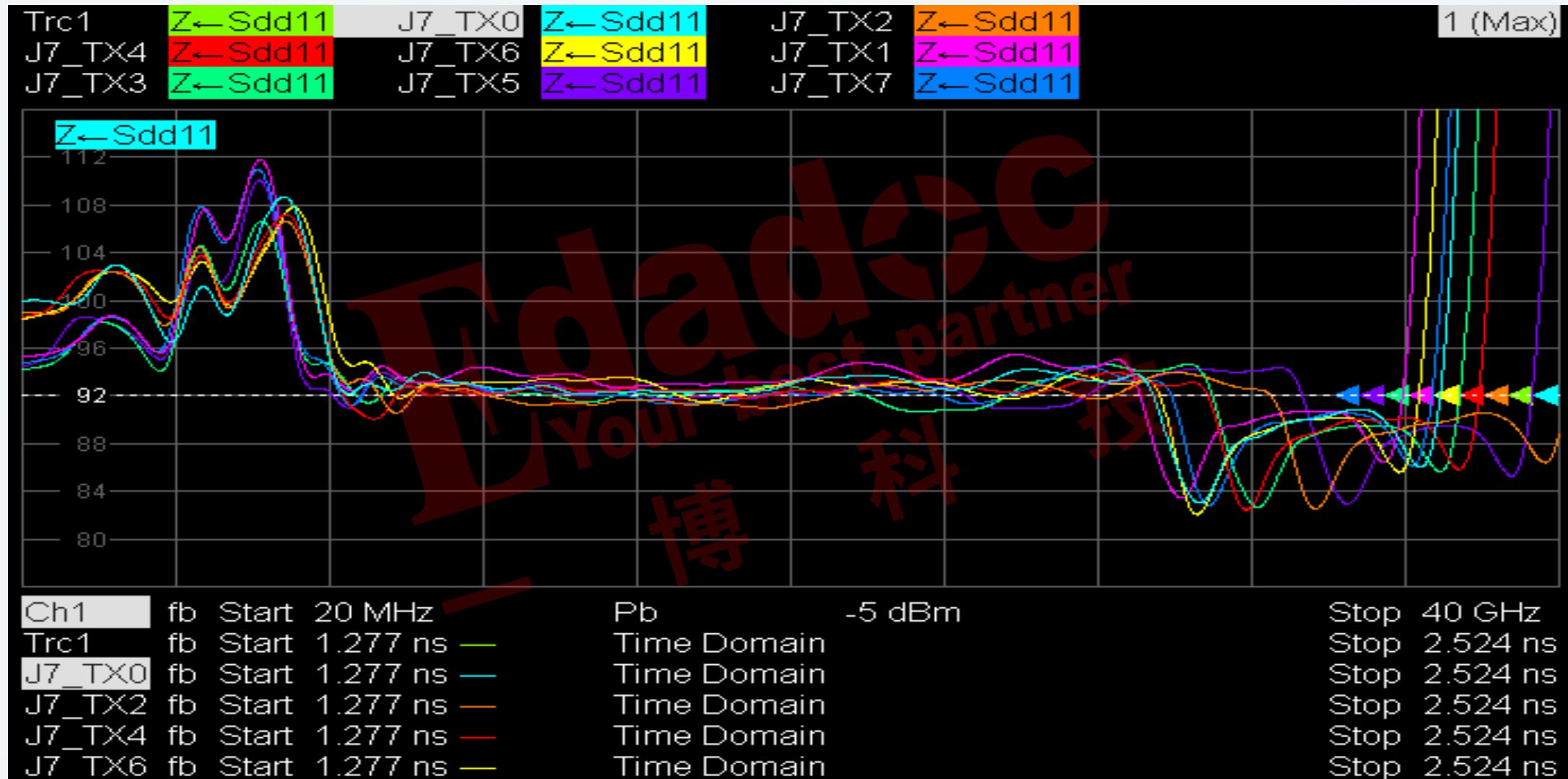
measurement	Summary
WidthAtBER0	3.755E-12
WidthAtBER1	4.694E-12
WidthAtBER2	6.477E-12
HeightAtBER0	0.028
HeightAtBER1	0.043
HeightAtBER2	0.079
Tmid	1.906E-11
Vlow	0.018
Vmid	0.017
Vupp	0.051
Hlow	3.661E-12
Hmid	4.224E-12
Hupp	5.914E-12
AVlow	0.233
AVmid	0.231
AVupp	0.224



measurement	Summary
WidthAtBER0	3.379E-12
WidthAtBER1	4.130E-12
WidthAtBER2	6.195E-12
HeightAtBER0	0.025
HeightAtBER1	0.040
HeightAtBER2	0.074
Tmid	1.906E-11
Vlow	0.016
Vmid	0.016
Vupp	0.048
Hlow	3.098E-12
Hmid	3.849E-12
Hupp	5.444E-12
AVlow	0.232
AVmid	0.230
AVupp	0.223

## 第二版加工后的阻抗测试

- 走线阻抗控制92欧姆再做一版，误码率测试提升了2个级别，接近1E-9。
- TDR阻抗测试结果如下：



1. 传输线阻抗是高速链路的重要影响因素，阻抗的变化对于不同速率的信号会有不同程度的影响；
2. 在大部分速率下（56Gbps及以下），传输线阻抗的设计值选择比起加工误差更影响信号质量；
3. 没必要纠结1欧姆左右的加工误差，测试的值本身也会受到各种外部因素的影响；
4. 112G以上的信号的确需要重视阻抗的设计值和加工误差，这个速率下传输线阻抗的变化对信号质量的影响的确变得很大。



# 一博珠海板厂一期已投产运营

一博珠海PCB板厂



一站式硬件创新平台

PCB设计--制板--元器件--焊接组装

一博旗下控股子公司，珠海全新板厂位于珠海金湾区，占地面积4.5万平方米，年产量180万平米，规划分两期建设，一期全面投产专注于高端快件，提供高品质的高多层、高速、高精密、HDI等PCB生产制造。二期提供中大批量高速、高多层PCB生产。

珠海板厂距离一博珠海基地17公里、20分钟车程，实现快速的PCB设计研发到高品质、短交期的PCB及PCBA生产服务。

一博助力客户缩短研发生产周期、聚焦客户痛点及难点，提供PCB设计、制板、焊接加工的一站式解决方案。





# 一博珠海板厂定位

<b>60:1</b> 成品孔厚径比	<b>120</b> 层 层数	<b>±5%</b> 阻抗控制精度
<b>≤8</b> 天 10-20层交付周期	<b>高端+快件</b> 工厂定位	<b>0.11</b> mm 机械孔钻孔孔径
<b>40</b> <small>um</small> 线宽线间距	<b>500+</b> <small>订单/天</small> 规划产量规模	<b>1-4</b> <small>mil</small> 背钻STUB

聚焦高端AI算力卡（高阶HDI）、高端服务器、ATE（晶圆测试）、工控、汽车电子、高端消费类、医疗、航空航天、网络设备、军工、光模块等产品。致力于推动国内PCB行业的技术进步，尤其是高速、高多层的复杂PCB产品的快速交付，20层及以下制板交期<8天，22层及以上在2周内交付，达到行业领先水平。产品广泛应用于工控、通讯、半导体测试、数据中心、AI算力等领域。



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